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Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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M65582AMF-XXXFP

NTSC TV Signal Processor with MCU

REJ03F0093-0100Z

Rev.1.0

Sep.19.2003

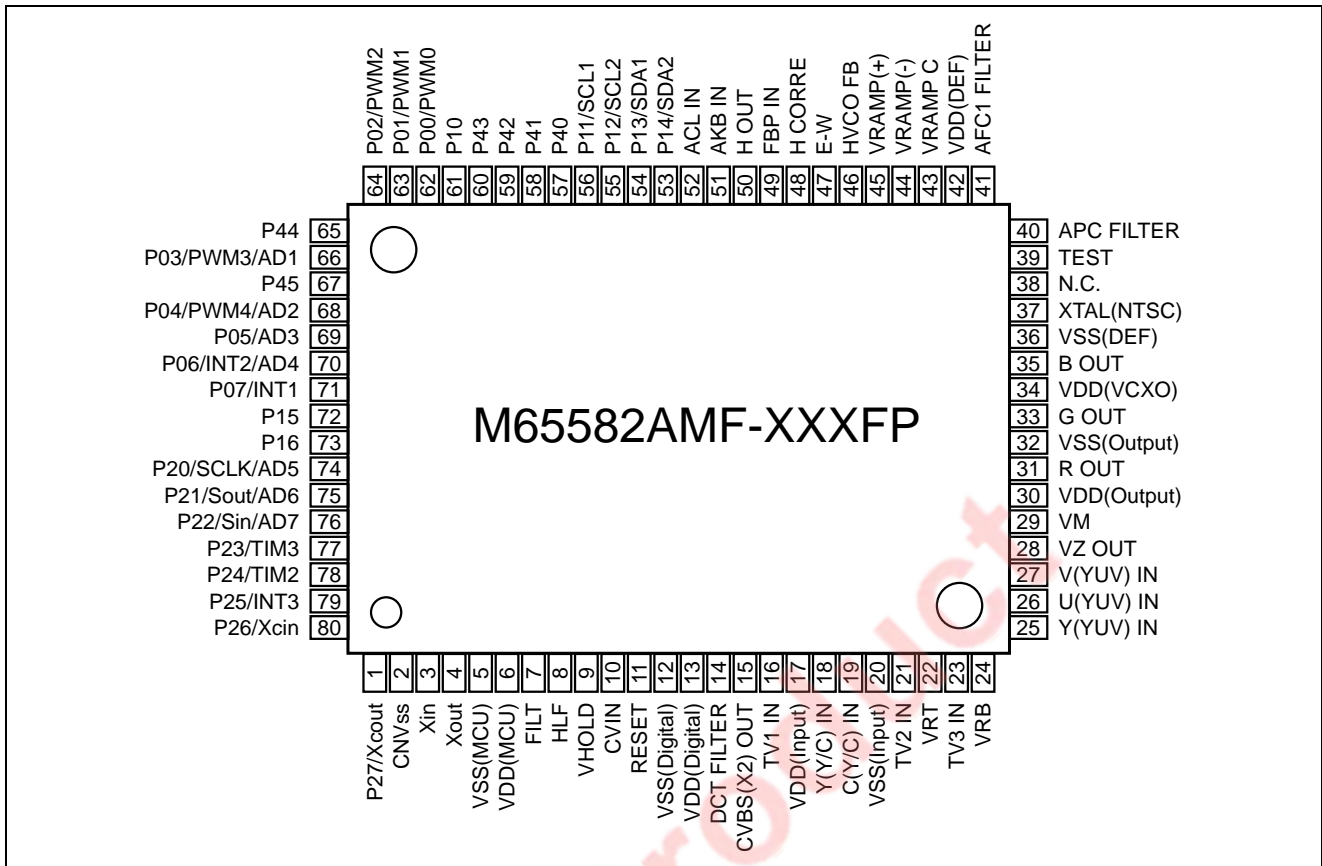
Features

- 1package solution with TV baseband signals (Video and Chroma) processor, deflection and 8bit MCU
- High quality picture by 2 Dimension Adaptive Y/C Separation of 3 Line type
- Built-in VM (Velocity Modulation) circuit emphasizing the picture outline by the changing of the Scanning Speed
- Built-in the correction circuits of the picture distortion which is EAST-WEST function etc. for Flat TV
- Available to use the software for best saled MCU M37272
- Available to input External Video signal, S Video signal and Component Video signal
- High performance OSD function with CCD and Half Tone Display
- Analog Video Switch with 5 Video Inputs Composite Video : 3ch, S Video : 1ch, Component Video : 1ch
- Built-in a high performance Blackstrech
- Built-in YNR
- Built-in 8bit MCU core M37272
ROM : 60Kbyte, RAM : 2048byte

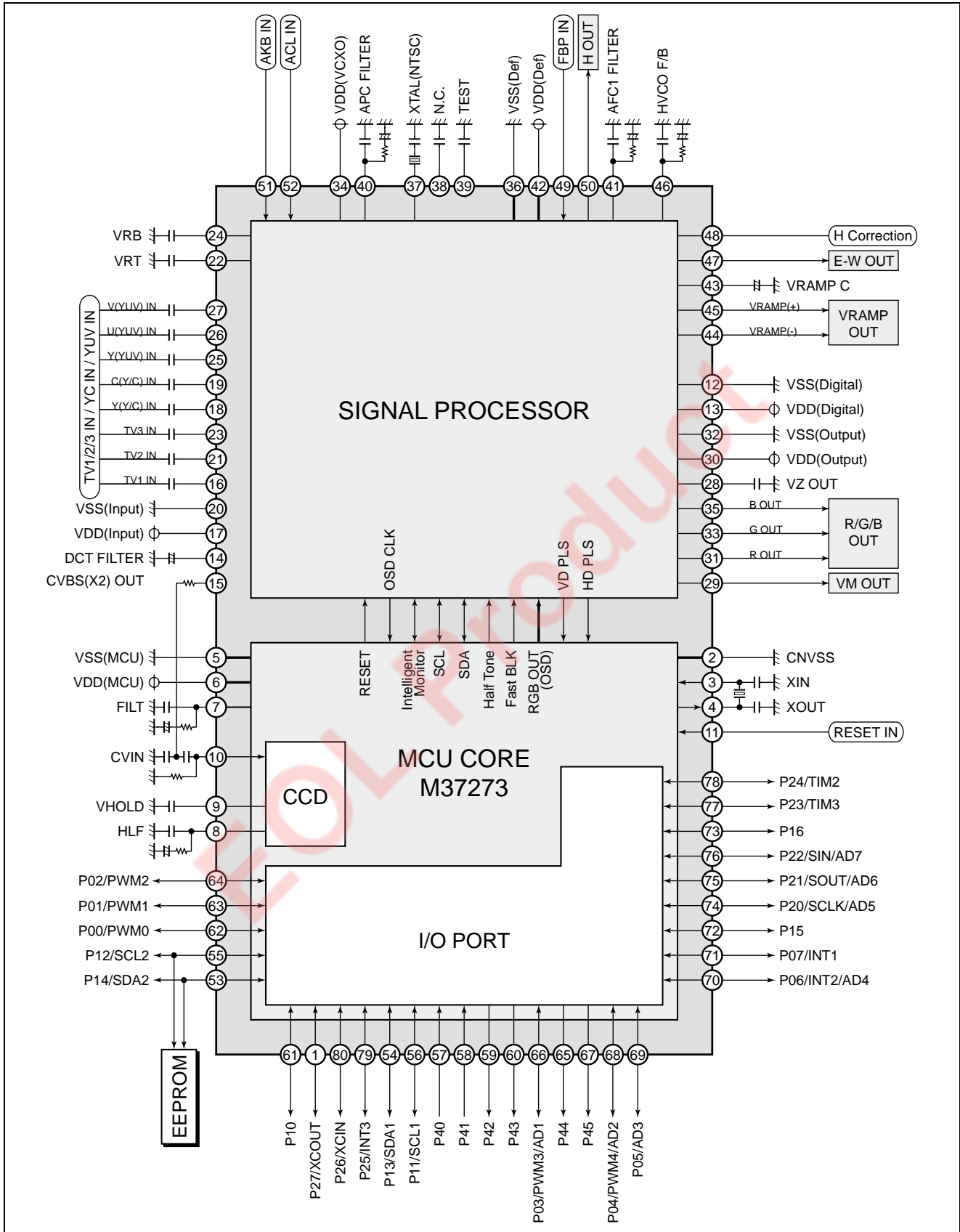
Applications

NTSC color television receivers

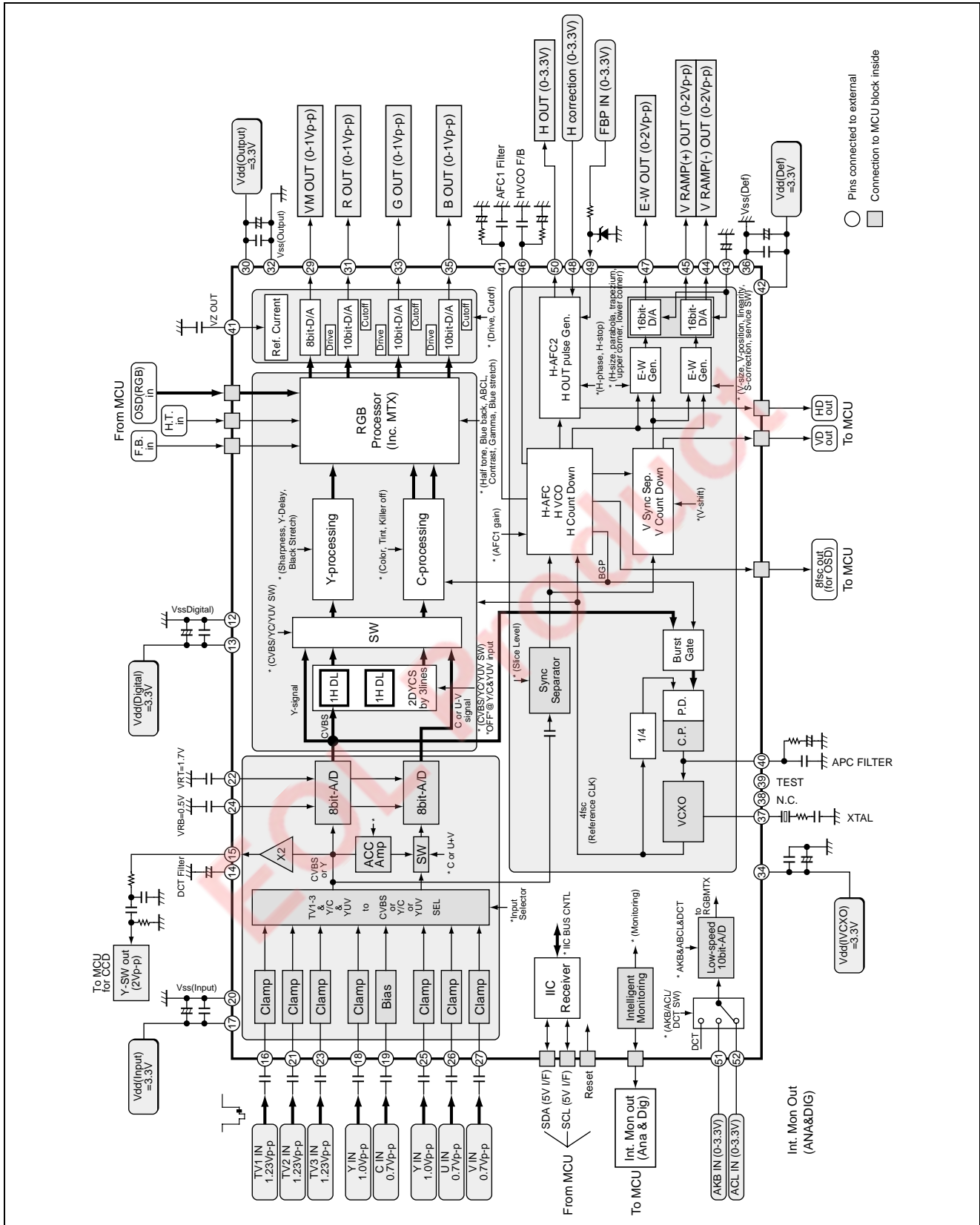
Pin Configuration



Block Diagram (Whole)



Block Diagram (ASIC)



Absolute maximum ratings

Parameter	Symbol	Ratings	Unit	Conditions
Supply voltage (MCU : 5V)	VDD (MCU)	-0.3 to 6.0	V	All voltage are based on Vss. Output transistors are cut off.
Supply voltage (ASIC : 3.3V)	VDD (ASIC)	-0.3 to 4.0	V	
Input Voltage (MCU)	VI (MCU)	-0.3 to Vcc+0.3	V	
Output Voltage (MCU)	VO (MCU)	-0.3 to Vcc+0.3	V	
Circuit current (MCU)	IOH (MCU)	0 to 1 (See note 1)	mA	
Circuit current (P00-P07, P10, P15, P16, P20-P27, P40-P45)	IOL1 (MCU)	0 to 2 (See note 2)	mA	
Circuit current (P11-P14)	IOL2 (MCU)	0 to 6 (See note 2)	mA	
Circuit current (P24-P27)	IOL3 (MCU)	10 (See note 3)	mA	
Digital input voltage	VID (ASIC)	-0.3 to Vcc+0.3	V	
Analog output current	IOOUT (ASIC)	-30	mA	
Power dissipation	Pd	2000	mW	
Thermal derating	Kt	20.0	mW/° C	
Operating temperature	Topr	-20 to 70	° C	
Storage temperature	Tstg	-40 to 125	° C	

Recommended Conditions

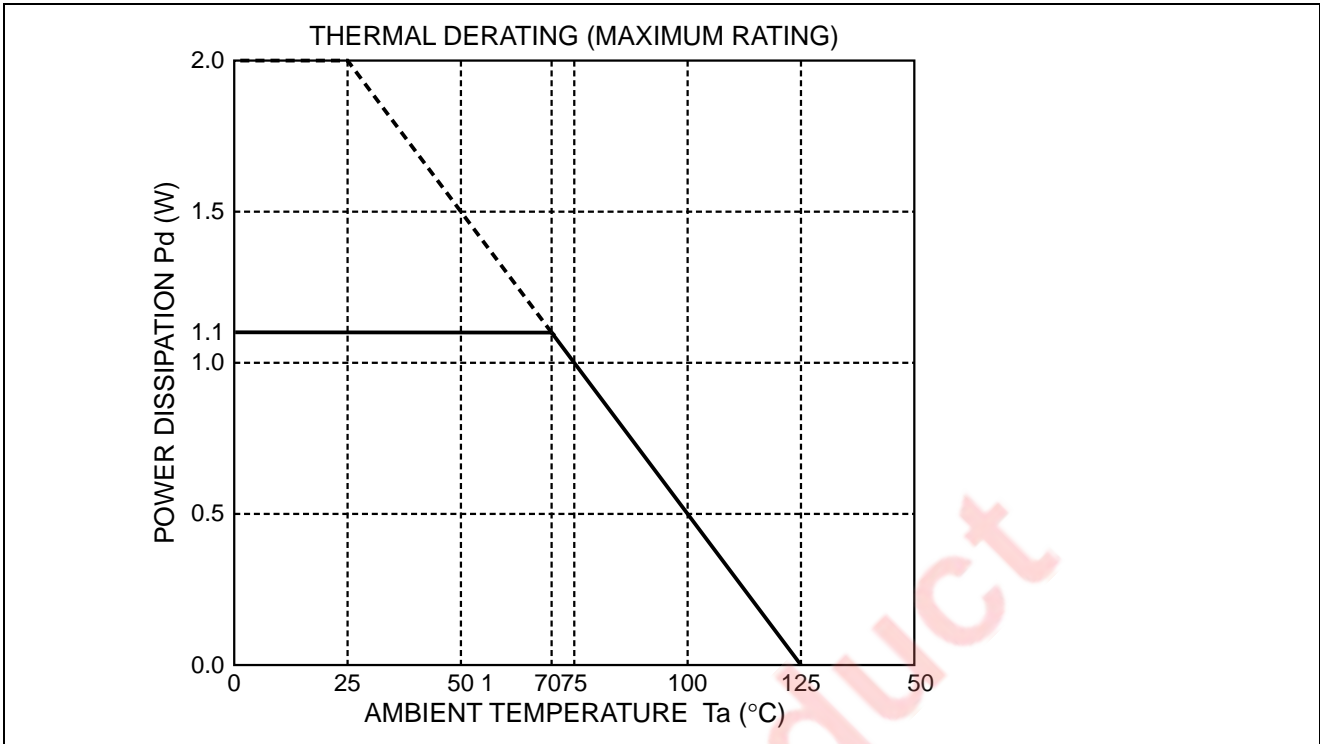
(Ta=25 to 70°C, Unless otherwise noted)

Parameter	Symbol	Limits			Unit
		Min.	Typ.	Max.	
Supply voltage (MCU) (See note 4)	VDD (MCU)	4.75	5.0	5.25	V
Supply voltage (Digital)	VDD (Digital)	3.13	3.3	3.47	V
Supply voltage (Input)	VDD (Input)	3.13	3.3	3.47	V
Supply voltage (Output)	VDD (Output)	3.13	3.3	3.47	V
Supply voltage (VCXO)	VDD (VCXO)	3.13	3.3	3.47	V
Supply voltage (DEF)	VDD (DEF)	3.13	3.3	3.47	V
Supply voltage (MCU)	VSS (MCU)	0	0	0	V
High loutput voltage P00-P07, P10-P16, P20-P27, P40-P45, RESET, X IN	VIH1 (MCU)	0.8 VDD		VDD	V
High loutput voltage SCL1, SCL2, SDA1, SDA2 (When using I2C -Bus)	VIH2 (MCU)	0.7 VDD		VDD	V
High loutput voltage FBP IN	VIH3 (ASIC)	0.8 VDD		VDD	V
Low loutput voltage P00-P07, P10-P16, P20-P27 P40-P45	VIL1 (MCU)	0		0.4 VDD	V
Low loutput voltage SCL1, SCL2, SDA1, SDA2 (When using I2C-Bus)	VIL2 (MCU)	0		0.3 VDD	V
Low loutput voltage (See note 6) RESETB, X IN, TIM2, TIM3, INT1, INT2, INT3, S IN, S CLK	VIL3 (MCU)	0		0.2 VDD	V
Low loutput voltage FBP IN	VIL4 (ASIC)	0		0.2 VDD	V
High average output current (See note 1) P10-P16, P20-P27, P40-P45	IOH (MCU)			1	mA

Parameter	Symbol	Limits			Unit
		Min.	Typ.	Max.	
Low average output current (See note 2) P00-P07, P10, P15, P16, P20-P27, P40-P45	IOL1(MCU)			2	mA
Low average output current (See note 2) P11-P14	IOL2(MCU)			6	mA
Low average output current (See note 3) P24-P27	IOL3(MCU)			10	mA
Oscillation frequency (for CPU operation) X IN (See note 5)	f(XIN) (MCU)	7.9	8.0	8.1	MHz
Oscillation frequency (for sub-clock operation) X CIN	f(XCIN) (MCU)	29	32	35	kHz
Input frequency TIM2, TIM3, INT1, INT2, INT3	fhs1 (MCU)			100	kHz
Input frequency S CLK	fhs2 (MCU)			1	MHz
Input frequency SCL1, SCL2	fhs3 (MCU)			400	kHz
Input amplitude video signal CV IN	VI (MCU)	1.5	2.0	2.5	V

- Note
- 1: The total current that flows out the MCU must be 20mA or less.
 - 2: The total input current to MCU (IOL1+IOL2) must be 30mA or less.
 - 3: The total average input current for ports P24-P27 to MCU must be 20mA or less.
 - 4: Connect 0.1 μ F or more capacitor externally between the power source pins VDD-VSS so as to reduce power source noise.
 - 5: Use a quartz-crystal oscillator or a ceramic resonator for the CPU oscillator circuit. When using the data slicer, use 8MHz.
 - 6: P06, P07, P23-P25 have the hysteresis when these pins are used as interrupt input pins or timer pins. P11-P14 have the hysteresis when these pins are used as multi-master I²C-Bus interface ports. P20-P22 have the hysteresis when these pins are used as serial I/O pins.
 - 7: Pin name in each parameter is described pin names.
 - (1) Dedicated pins: dedicated pin name.
 - (2) Double-/Triple-function ports.
 - When the same limits: I/O port name.
 - When the limits of function except ports are different from I/O port limits: function pin name.

Thermal derating



I²C busI²C bus table

Slave address	Sub address	D7	D6	D5	D4	D3	D2	D1	D0	Standard data		
BAh	00h					V STOP	Power Down		H STOP	00h		
BAh	01h	Input Video SW					SAW Filter		Line-delay Number		08h	
BAh	02h	Pedestal Clamp				VRT Voltage					08h	
BAh	04h		Aperture Frequency			Sharpness Noise Coring Level					10h	
BAh	05h	EHT				Sharpness Max Gain					0Fh	
BAh	06h		Y Delay		YNR SW	YNR Coring Level					6Fh	
BAh	08h	Tint									40h	
BAh	09h	Color									40h	
BAh	0Ah	Contrast									40h	
BAh	0Bh	Half Tone			OSD Level (R)							20h
BAh	0Ch	RGB MTX			OSD Level (G)							A0h
BAh	0Dh	OSD COMP			OSD Level (B)							20h
BAh	0Eh	Brightness									80h	
BAh	0Fh	AFC Free Run	H AFC Gain	H AFC2 Phase								20h
BAh	10h	RGB P-ON Mute	Y THR 2D	R OUT Mute	Y 2D Fix	G OUT Mute	B OUT Mute	C BPF Fix	Y Mute	02h		
BAh	11h					MANEXP		ALFA		02h		
BAh	12h	RGB ON	FSC SEL	FSC ORG		Blue Stretch		Gamma		80h		
BAh	13h							H OUT Duty	H Free Up	02h		
BAh	14h	V BLK Stop		V Size								20h
BAh	15h			V Linearity								20h
BAh	16h	Cutoff (R) L									00h	
BAh	17h	Cutoff (R) H	Drive (R)								C0h	
BAh	18h	Cutoff (G) L									00h	
BAh	19h	Cutoff (G) H	Drive (G)								C0h	
BAh	1Ah	Cutoff (B) L									00h	
BAh	1Bh	Cutoff (B) H	Drive (B)								C0h	
BAh	1Ch	Analog Monitoring Point									00h	
BAh	1Dh		TEST I/O	Digital Monitoring Point								00h
BAh	30h	INV 14H CLK	14H CLK DLY		INV DS CLK	DS CLK DLY		A/D CLK DLY		03h		
BAh	32h	VJP Width	VJP SW				ABL SEL	UV LPF ON		04h		
BAh	33h	Black Stretch Time 1				Black Stretch Time 2					F4h	
BAh	34h		DS D/A CLK CTL	DS D/ADither	ABL Speed					04h		
BAh	35h	ABL SPE				ABL ASPE					92h	
BAh	36h		ABL Time Constant			ABL Gain					05h	
BAh	37h		UV Dither Test Enable				UV Dither ON	ABL ASPE2			02h	
BAh	38h	AKB Mode	EHT Gain	AKB P								60h
BAh	39h						YCS H BPF Back	YCS H BPF Front		03h		
BAh	3Ah	Sharpness Overshoot Gain									20h	
BAh	3Bh	Sharpness Preshoot Gain									20h	
BAh	3Dh		BS T2 IF ON	THR NZV 1		Black Stretch Depth		Black Stretch SW		34h		
BAh	3Eh	THR NZV 2									FFh	
BAh	3Fh	THR NZH 1									FFh	
BAh	40h	THR NZH 2									FFh	
BAh	41h	Killer Level									01h	
BAh	42h	AMP CTL			RRAY							C0h
BAh	43h	AMP1 OFF L									5Ah	
BAh	44h	AMP1 OFF H	AMP1 ON								04h	
BAh	45h		ACC SW	MV2 SW	MV1 SW	MV					30h	
BAh	46h	4FSC SW	HD SW	Killer SW	BGP POS							68h
BAh	47h	Force Killer	Clamp BITSEL		OSD Limit	C Delay		AVE SEL		42h		
BAh	48h	AMP3 ACC	V Mask Time			AMP TIM		B2 AVE SEL		00h		
BAh	49h	YUV MPX SEL	YUV CXUV	YUV UV Inv.	UV Gain	Free Run Offset					00h	
BAh	4Bh	Killer Threshold									01h	
BAh	4Ch	SWAP	Free Run	BG Start							90h	
BAh	4Dh						BW SEL	BW DET		01h		
BAh	4Eh	Skew Corrector			VCXO CTRL						Skew Co. Ini.	14h
BAh	4Fh	H Charge Pump			Ramp Slew Rate		Auto Slice Up	Auto Slice Down		78h		
BAh	50h	Ref Charge Pump			AFC1 Pull-in	VCXO Free Run		Ref VCO		61h		
BAh	51h	H VCO Free Run									00h	
BAh	52h	I/M Test	LPF SYNC	V Ramp Filter OFF	Macro OFF	AFC2 Gain		V Sag	Sync Sep Mask	2Ch		
BAh	53h	EWW V Reset	Sync Slice Level (V)		Sync Slice Level (H)		4FSC SEL 2	8FSC SEL	B PLL C.P.	67h		
BAh	54h	V-Latch OFF	H BLK Stop	V CD Mode 2	BGP C	VD Delay	V Free	V CD Mode		29h		

Note: Sub address 03h, 07h, 1Eh-2Fh, 31h, 3Ch, 4Ah and 5Eh-64h are not operational.

Slave address	Sub address	D7	D6	D5	D4	D3	D2	D1	D0	Standard data	
BAh	55h	AMP CTRL EN			AMP2 ON					84h	
BAh	56h				AMP3 ON					04h	
BAh	57h				AMP2 OFF L					40h	
BAh	58h									AMP2 OFF H	00h
BAh	59h				AMP3 OFF L					40h	
BAh	5Ah				Weak Sig Det Vth					AMP3 OFF H	00h
BAh	5Bh	Weak Sig Chroma ATT			Weak Sig Video ATT			Spot Killer		00h	
BAh	5Ch				TEST I/O Control					00h	
BAh	5Dh	XTEST RST	LPF SYNC ON	Sync Slice Level (V/W)		MEM TEST	TEST SEL			80h	
BAh	65h				V Aperture Coring Level					00h	
BAh	66h	V Aperture Gain			V Aperture Max Gain					0Fh	
BAh	67h	VM POL	VM Width		VM Coring Level					00h	
BAh	68h	VM Gain			VM Max Gain					8Fh	
BAh	69h	Black Stretch Start Point	Y Clamp ON	Y Clamp Fix	VM Delay					E6h	
BAh	6Ah				S Correction					00h	
BAh	6Bh				H Size					20h	
BAh	6Ch				Parabola					20h	
BAh	6Dh				Trapezium					20h	
BAh	6Eh				Upper Corner					20h	
BAh	6Fh				Lower Corner					20h	
BAh	70h				LIM					0Fh	
BAh	71h				V Position					20h	
BAh	72h				AFC Bow					20h	
BAh	73h				AFC Angle					20h	
BAh	74h	V Free 2	AFC2 SEL	Angle OFF	AFC2 Ramp Pos					08h	
BAh	75h	H BLK F Position			Clock SEL					81h	
BAh	76h	H BLK R Position								80h	
BAh	77h	FBP BLK		V BLK Pos	AKB Ref PLS Pos	V BLK Half Kill				02h	
BAh	78h	VREF SEL	V Sync LPF 2		V Sync LPF 1	A/D Read Page				04h	
BAh	79h				DCT Vth					1Eh	
BAh	7Ah				DCT Gain					00h	
BAh	7Bh				AKB LIM 1					04h	
BAh	7Ch				AKB LIM 2					0Ch	
BAh	7Dh				AKB LIM 3					15h	
BAh	7Eh				AKB ADD 1					02h	
BAh	7Fh				AKB ADD 2					06h	
BAh	80h				AKB COMP (R) L					00h	
BAh	81h				AKB COMP (G) L					00h	
BAh	82h				AKB COMP (B) L					00h	
BAh	83h	V EN OFF	AKB Enable	AKB COMP (B) H		AKB COMP (G) H		AKB COMP (R) H		2Ah	
BAh	84h				A/D D/A Test EN					00h	
BAh	85h				AXIS HYS					1Eh	
BAh	86h	AVE SEL AV			ROM HYS					CAh	
BAh	87h				B2 COMP					00h	
BAh	88h	V In Offset			U In Offset					88h	
BAh	89h	AKB SEL		AKB Speed		CLK SEL SAR A/D		ACL Gain	ACL ON	00h	
BAh	8Ah	V PLS Width		VM Gain 2		DS CLK Latch Pol	DS CLK Latch ON	DS CLK DIV SEL		40h	
BAh	8Bh				AKB SWERR					7Ch	
BAh	8Ch				AKB ERRC					14h	
BAh	8Dh				AKB SWPON					1Eh	
BAh	8Eh				AKB PWERRC					02h	

BBh	90h	H COIN	S Det	AKB END	AKB NG	DETNZ				
BBh	91h	B2 ROM <8>	Killer Status	V COIN	B/W Out	Still Det	MV 180	K MONI		
BBh	92h				B2 ROM <7:0>					
BBh	93h				AKB A/D (R) <7:0>					
BBh	94h	AKB A/D (R) <9:8>		AKB New (R)	C Gain					
BBh	95h				AKB A/D (G) <7:0>					
BBh	96h	AKB A/D (G) <9:8>		AKB New (G)						
BBh	97h				AKB A/D (B) <7:0>					
BBh	98h	AKB A/D (B) <9:8>		AKB New (B)						
BBh	99h				Y A/D <7:0>					
BBh	9Ah				C A/D <7:0>					
BBh	9Bh	0	0	1 0						

I²C bus function

Sub address	Data	Bit	Function	Description	Note
00h	D0	1	H STOP	H pulse stop	
	D1-D2	2	Power Down	Power Down control (0: normal, 1: PD0, 2: PD1, 3: PD2)	
	D3	1	V STOP	V output stop	
01h	D0	1	Line-delay Number	Y/C separation mode (0: 3-line mode, 1: 2-line mode)	
	D2	1	SAW Filter	Chroma BPF to high	
	D3-D7	5	Input Video SW	Input video SW (01: TV1 IN, 02: TV2 IN, 04: TV3 IN, 08: Y/C IN, 10: YUV IN)	
02h	D3-D4	2	VRT Voltage	A/D Reference (0: 1.1V, 1: 1.2V, 2: 1.3V, 3: 1.4V)	
	D7	1	Pedestal Clamp	Input clamp select (0: pedestal clamp, 1: sync-tip clamp)	
04h	D0-D3	4	Sharpness Noise coring level	Sharpness coring level (0: minimum — F: maximum)	V Latch
	D4-D5	2	Aperture Frequency	Sharpness fo (0: 2-clk ←→ 3: 5-clk)	V Latch
05h	D0-D3	4	Sharpness Max Gain	Sharpness limiter level (0: minimum — F: maximum)	V Latch
	D4-D7	4	EHT	EHT gain control (0: minimum — F: maximum)	V Latch
06h	D0-D3	4	YNR Coring Level	YNR limiter level (0: minimum — F: maximum)	V Latch
	D4	1	YNR SW	YNR enable	V Latch
	D5-D6	2	Y Delay	Y delay time (0: Onsec — 3: 210nsec)	V Latch
08h	D0-D6	7	Tint	Tint level control (00: -45° — 7F: +45°)	V Latch
09h	D0-D6	7	Color	Color level control (00: 0% — 7F: 200%)	V Latch
0Ah	D0-D6	7	Contrast	Contrast control (00: 0% — 7F: 200%)	V Latch
0Bh	D0-D5	6	OSD Level (R)	R OSD level (00: 0% — 7F: maximum)	V Latch
	D6-D7	2	Half Tone	Half tone level control (Picture/OSD ratio 0: 50%/50% — 3: 12.5%/87.5%)	V Latch
0Ch	D0-D5	6	OSD Level (G)	G OSD level (00: 0% — 7F: maximum)	V Latch
	D6-D7	2	RGB MTX	RGB matrix ratio (0: 12/8, 1: 13/8, 2: 14/8, 3: 14/8)	V Latch
0Dh	D0-D5	6	OSD Level (B)	B OSD level (00: 0% — 7F: maximum)	V Latch
	D6-D7	2	OSD COMP	Contrast clip level for OSD (0: low — 3: high)	V Latch
0Eh	D0-D7	8	Brightness	Brightness control (00: -50% — 7F: +50%)	V Latch
0Fh	D0-D5	6	H AFC2 Phase	H position (00: +2.6μsec — 7F: -2.6μsec)	
	D6	1	H AFC Gain	AFC1 Gain (0: low, 1: high)	
	D7	1	AFC Free Run	AFC1 Force free-run	
10h	D0	1	Y Mute	Y output mute	
	D1	1	C BPF Fix	Chroma signal generate from H/V BPF only	
	D2	1	B OUT Mute	B output mute	
	D3	1	G OUT Mute	G output mute	
	D4	1	Y 2D Fix	Y signal generate from 2DYCS	
	D5	1	R OUT Mute	R output mute	
	D6	1	Y THR 2D	Y signal through 2D YCS	
11h	D0-D1	2	ALFA	Adaptive detection sensitivity (0: minimum — 3: maximum)	
	D2-D3	1	MANEXP	Y/C separation force select (0: adaptive, 2: V, 3: H/V)	
12h	D0-D1	2	Gamma	Gamma control (0: none — 3: deep)	
	D2-D3	2	Blue Stretch	Blue stretch control (0: none — 3: deep)	
	D4-D5	2	FSC ORG	Chroma decoder phase select	
	D6	1	FSC SEL	Chroma decoder clock select	
	D7	1	RGB ON	RGB output (0: RGB mute except OSD, 1: RGB output)	
13h	D0	1	H Free Up	AFC1 Free-run frequency up (about 700Hz)	
	D1	1	H OUT Duty	H pulse width (0: 25μsec, 1: 19μsec)	
14h	D0-D5	6	V Size	V ramp amplitude (00: -20% — 3F: +20%)	
	D7	1	V BLK Stop	V blanking off	
15h	D0-D5	6	V Linearity	V linearity (00: -3% — 3F: +3%)	
16h	D0-D7	9	Cutoff (R)	R cutoff control (000: dark — 1FF: light)	V Latch
17h	D7				
	D0-D6	7	Drive (R)	R drive control (00: -2.5dB — 7F: +3.5dB)	V Latch
18h	D0-D7	9	Cutoff (G)	G cutoff control (000: dark — 1FF: light)	V Latch
19h	D7				
	D0-D6	7	Drive (G)	G drive control (00: -2.5dB — 7F: +3.5dB)	V Latch
1Ah	D0-D7	9	Cutoff (B)	B cutoff control (000: dark — 1FF: light)	V Latch
1Bh	D7				
	D0-D6	7	Drive (B)	B drive control (00: -2.5dB — 7F: +3.5dB)	V Latch
1Ch	D0-D3	4	Analog Monitoring Point	Intelligent monitoring output select (Analog)	
1Dh	D0-D4	5	Digital Monitoring Point	Intelligent monitoring output select (Digital)	
	D5	1	TEST I/O	Intelligent monitoring output enable (Digital)	
30h	D0-D1	2	A/D CLK DLY	A/D clock delay adjust (0: none — 3: delay)	
	D2-D3	2	DS CLK DLY	ΔΣ D/A (for V-ramp and E-W) clock delay adjust (0: none — 3: delay)	
	D4	1	INV DS CLK	ΔΣ D/A (for V-ramp and E-W) clock polarity (0: none — 1: invert)	

Sub address	Data	Bit	Function	Description	Note
30h	D5-D6	2	14H CLK DLY	4fsc clock delay adjust (0: none — 3: delay)	
	D7	1	INV 14H CLK	4fsc clock polarity (0: none, 1: invert)	
32h	D1	1	UV LPF ON	UV LPF (digital) enable	
	D2	1	ABL SEL	ABL function (0: enable, 1: disenable)	
	D6	1	VJP SW	Jump SW enable	
	D7	1	VJP Width	Jump pulse width (0: normal, 1: wide +2-line)	
33h	D0-D3	4	Black Stretch Time 2	Black stretch recover time (0: slow — F: fast)	
	D4-D7	4	Black Stretch Time 1	Black stretch attack time (0: slow — F: fast)	
34h	D2-D3	2	ABL Speed	ABL processing speed (0: X1, 1: X2, 2: X4, 3: X8)	
	D4	1	DS D/A Dither	$\Delta\Sigma$ D/A (for V-Ramp and E-W) dither enable	
	D5-D6	2	DS D/A CLK CTL	$\Delta\Sigma$ D/A (for V-Ramp and E-W) clock select (0: 28M, 1: 24M, 2: 14M, 3: 16M)	
35h	D0-D3	4	ABL ASPE	ABL attack speed (0: slow — 7: fast)	
	D4-D7	4	ABL SPE	ABL recover speed (0: slow — 7: fast)	
36h	D0-D3	4	ABL Gain	ABL gain control (0: minimum — 7: maximum)	
	D4-D6	3	ABL Time Constant	ABL time constant (0: slow — 7: fast)	
37h	D0-D1	2	ABL ASPE 2	ABL attack speed 2 (0: slow — 7: fast)	
	D2	1	UV Dither ON	UV dither enable	
	D3-D5	3	UV Dither Test Enable	UV dither test select	
38h	D0-D5	6	AKB P	AKB reference pulse height (00: minimum — 3F: maximum)	
	D6	1	EHT Gain	EHT gain up (0: normal, 1: high)	
	D7	1	AKB Mode	AKB mode select (0: differential mode, 1: absolute mode)	
39h	D0	1	YCS HBPFF Front	Y/C separation front BPF band width (0: wide, 1: narrow)	
	D1-D2	2	YCS HBPFF Back	Y/C separation rear BPF band width (0: none, 1: wide — 2 and 3: narrow)	
3Ah	D0-D5	6	Sharpness Overshoot Gain	Sharpness overshoot gain (00: soft — 3F: sharp)	V Latch
3Bh	D0-D5	6	Sharpness Preshoot Gain	Sharpness preshoot gain (00: soft — 3F: sharp)	V Latch
3Dh	D0	1	Black Stretch SW	Black stretch SW (0: disenable, 1: enable)	
	D1-D3	3	Black Stretch Depth	Black stretch depth (0: shallow — 7: deep)	
	D6	1	BS T2 IF ON	Black stretch recover time constant (0: slow, 1: fast)	
	D4-D5	10	THR NZV	Noise detection threshold level in field (000: minimum — 3FF: maximum)	
3Eh	D0-D7				
3Fh	D0-D7	16	THR NZH	Noise detection threshold level in line (0000: minimum — FFFF: maximum)	
40h	D0-D7				
41h	D0-D6	7	Killer Level	Color Killer threshold level (00: deep — 7F: shallow)	
42h	D0-D5	6	RRAY	R-Y phase offset (00: 0° — 3F: 90°)	
	D6-D7	2	AMP CTL	Analog ACC amp maximum gain (0: 0dB — 3: +30dB)	
43h	D0-D7	9	AMP1 OFF	Analog ACC amp #1 on – >off level (000: minimum — 1FF: maximum)	
44h	D7				
	D0-D6	7	AMP1 ON	Analog ACC amp #1 off – >on level (00: minimum — 7F: maximum)	
45h	D0-D3	4	MV	Macro vision (burst) detect level	
	D4	1	MV1 SW	Macro vision (burst) detect enable	
	D5	1	MV2 SW	Macro vision (burst) detect position	
	D6	1	ACC SW	ACC enable	
46h	D0-D4	5	BGP POS	BGP (for chroma decoder) position	
	D5	1	Killer SW	Killer detector mode select (0: synchronous detect, 1: amplitude detect)	
	D6	1	HD SW	HD out (for OSD) select (0: FBP, 1: AFC1 pulse)	
	D7	1	4FSC SW	A/D-LOGIC clock swap	
47h	D0-D1	2	AVE SEL	Chroma decoder time constant (0: 32H, 1: 16H, 2: 8H, 3: 1H)	
	D2-D3	2	C Delay	Chroma delay time (0: none — 3: delay)	
	D4	1	OSD Limit	OSD limit select	
	D6	1	Clamp BITSEL	Y digital clamp time constant (0: fast, 1: slow)	
	D7	1	Force Killer	Forced killer	
48h	D0-D1	2	B2 AVE SEL	Accumulation time control of demodulation	
	D2-D3	2	AMP TIM	Analog ACC hysteresis select	
	D4-D6	3	V Mask Time	V masking time for demodulation	
	D7	1	AMP3 ACC	ACC maximum gain	
49h	D0-D3	4	Free Run Offset	VCXO free-run frequency adjust	
	D4	1	UV Gain	U/V gain up	
	D5	1	YUV UV Inv.	U/V invert	
	D6	1	YUV CXUV	YC/YUV select	
	D7	1	YUV MPX SEL	U/V multiplex select (0: 2fsc, 1: fsc)	
4Bh	D0-D1	2	Killer Threshold	PLL stop burst level	
4Ch	D0-D5	6	BG Start	BGP (for PLL) timing control	
	D6	1	Free Run	VCXO force free-run	
	D7	1	SWAP	Burst PLL polarity (0: reverse, 1: normal)	
4Dh	D0-D1	2	BW DET	PLL Killer threshold level	

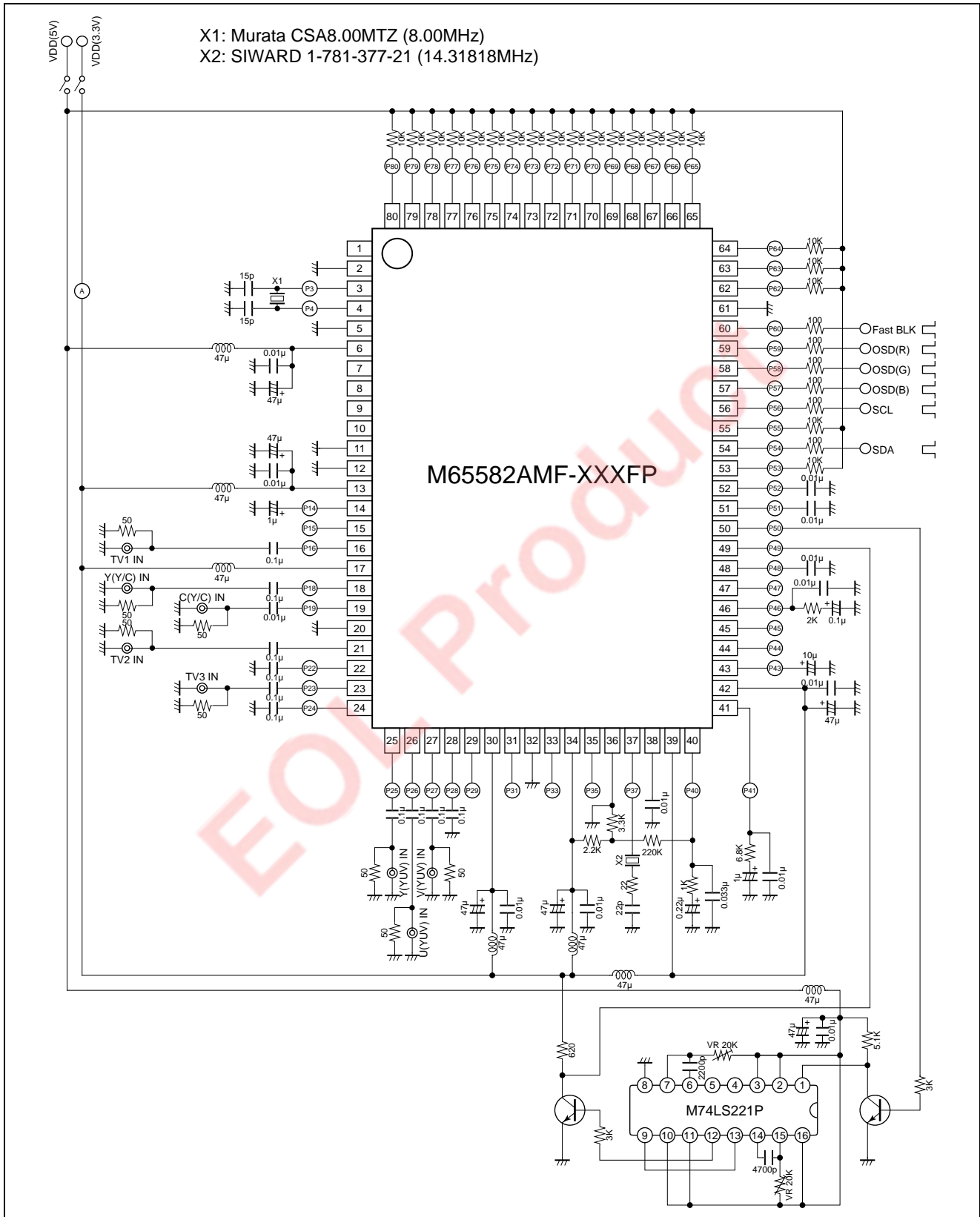
Sub address	Data	Bit	Function	Description	Note
4Dh	D2	1	BW SEL	$\Delta\Sigma$ D/A clock invert	
4Eh	D0	1	Skew Co Ini.	Skew corrector reference phase	
	D1-D4	4	VCXO CTRL	VCXO phase adjust	
	D5-D7	3	Skew Corrector	Skew corrector phase control	
4Fh	D0-D1	2	Auto Slice Down	Auto slicer level down (0: up — 3: down)	
	D2	1	Auto Slice Up	Auto slicer level up	
	D3-D4	2	Ramp Slew Rate	AFC2 Ramp slew rate	
	D5-D7	3	H Charge Pump	AFC1 charge pump current (4: minimum – 5 – 6 – 7 – 0 – 1 – 2 – 3: maximum)	
50h	D0	1	Ref VCO	Ref PLL loop gain up	
	D1-D2	2	VCXO Free Run	VCXO f_0 adjust	
	D4	1	AFC1 Pull-in	AFC1 pull-in range wide	
	D5-D7	3	Ref Charge Pump	Ref PLL charge pump current (4: minimum – 5 – 6 – 7 – 0 – 1 – 2 – 3: maximum)	
51h	D0-D7	8	H VCO Free Run	H VCO f_0 adjust (In case of data is XYh, X decrease the f_0 , and Y increase the f_0)	
52h	D0	1	Sync Sep Mask	Sync separator masking control	
	D1	1	V Sag	V sag prevent on	
	D2-D3	2	AFC2 Gain	AFC2 gain control (0: fast — 3: slow)	
	D4	1	Macro OFF	Top vend (when macrovision) prevent off	
	D5	1	V Ramp Filter OFF	V Ramp and E-W output filter off	
	D6	1	LPF SYNC	Pre sync separation LPF f_0 becomes low	
	D7	1	I/M Test	Intelligent monitoring signal (Digital) enable to output to pin 51	
53h	D0	1	B PLL C.P.	Chroma APC charge pump current up (0: normal, 1: X5)	
	D1	1	8FSC SEL	H rate clock select (0: 12MHz, 1: 4fsc skew clock)	
	D2	1	4FSC SEL 2	4fsc skew force off (0: H rate clock, 1: Burst rate clock)	
	D3-D4	2	Sync Slice Level (H)	Sync slice level (H sync separation)	
	D5-D6	2	Sync Slice Level (V)	Sync slice level (V sync separation)	
	D7	1	EWV V Reset	$\Delta\Sigma$ D/A V reset on	
54h	D0-D1	2	V CD Mode	V detect window switch timing (0: 5H, 1: 3H, 2: 1H, 3: force 1 window)	
	D2	1	V Free	Force V free-run	
	D3	1	VD Delay	VD pulse delay	
	D4	1	BGP C	BGP (for deflection block) width (0: normal, 1: Don't use. Useful only test mode)	
	D5	1	V CD Mode 2	V sub-counter enable	
	D6	1	H BLK Stop	H blanking off	
	D7	1	V-Latch OFF	IIC V latch off (for test)	
55h	D0-D6	7	AMP2 ON	Analog ACC amp #2 off – >on level (00: minimum — 7F: maximum)	
	D7	1	AMP CTRL EN	Analog ACC amp #1, #2 and #3 enable	
56h	D0-D6	7	AMP3 ON	Analog ACC amp #3 off – >on level (00: minimum — 7F: maximum)	
57h	D0-D7	9	AMP2 OFF	Analog ACC amp #2 on – >off level (000: minimum — 1FF: maximum)	
58h	D0				
59h	D0-D7	9	AMP3 OFF	Analog ACC amp #3 on – >off level (000: minimum — 1FF: maximum)	
5Ah	D0				
	D1-D3	3	Weak Sig Det Vth	Noise detect level of RF weak signal (0: minimum — 7: maximum)	
5Bh	D0	1	Spot Killer	Force spot Killer	
	D1-D3	3	Weak Sig Video ATT	Video attenuation control of RF weak signal (0: no attenuation — 7: maximum)	
	D4-D6	3	Weak Sig Chroma ATT	Chroma attenuation control of RF weak signal (0: no attenuation — 7: maximum)	
5Ch	D0-D7	8	TEST I/O Control	Test mode I/O control (only factory use)	
5Dh	D0-D2	3	TEST SEL	Test mode select (only factory use)	
	D3	1	MEM TEST	Memory test mode (only factory use)	
	D4-D5	2	Sync Slice Level (V/W)	Sync slice level (V sync separation within narrow window)	
	D6	1	LPF SYNC ON	Pre sync separation LPF enable	
	D7	1	XTEST RST	Test mode select (only factory use)	
65h	D0-D3	4	V Aperture Coring Level	V aperture coring level (0: minimum — F: maximum)	V Latch
66h	D0-D3	4	V Aperture Max Gain	V aperture limit level (0: minimum — F: maximum)	V Latch
	D4-D7	4	V Aperture Gain	V aperture gain (0: minimum — F: maximum)	V Latch
67h	D0-D3	4	VM Coring Level	VM coring level (0: minimum — F: maximum)	V Latch
	D4-D5	2	VM Width	VM width (0: minimum — 3: maximum)	V Latch
	D6	1	VM POL	VM polarity	V Latch
68h	D0-D3	4	VM Max Gain	VM limit level (0: minimum — F: maximum)	V Latch
	D4-D7	4	VM Gain	VM gain (0: minimum — F: maximum)	V Latch
69h	D0-D3	4	VM Delay	VM output delay (0: forward — F: delay)	V Latch
	D4	1	Y Clamp Fix	Y digital clamp control 1 (0: Y digital clamp enable, 1: Y digital clamp disable)	
	D5	1	Y Clamp ON	Y digital clamp control 2 (0: clamp level is held, 1: clamp level is refreshed at all time)	
	D6-D7	2	Black Stretch Start Point	Black stretch start point (0: 25%, 1: 31%, 2: 38%, 3: 44%)	
6Ah	D0-D5	6	S Correction	V Ramp S correction (00: 0% — 3F: +3%)	
6Bh	D0-D5	6	H Size	E-W output DC level (00: +250mV — 3F: -250mV)	
6Ch	D0-D5	6	Parabola	E-W output amplitude (00: 0.1V _{p-p} — 3F: 0.7V _p)	

Sub address	Data	Bit	Function	Description	Note
6Dh	D0-D5	6	Trapezium	E-W trapezium (00: -50% — 3F: +50%)	
6Eh	D0-D5	6	Upper Corner	E-W upper corner (00: -200% — 3F: +200%)	
6Fh	D0-D5	6	Lower Corner	E-W lower corner (00: -200% — 3F: +200%)	
70h	D0-D3	4	LIM	Chroma detect level for 2D YCS (0: minimum — F: no limit)	
71h	D0-D5	6	V Position	V Ramp output DC level (00: -10% — 3F: +10%)	
72h	D0-D5	6	AFC Bow	AFC Bow (00: +1.5μsec — 3F: -1.5μsec)	
73h	D0-D5	6	AFC Angle	AFC Angle (00: +/-1.5μsec — 3F: +/-1.5μsec)	
74h	D0-D3	4	AFC2 Ramp Pos	AFC2 Ramp position (0: -5.2μsec — F: +5.2μsec)	
	D4	1	Angle OFF	AFC Angle/Bow disable	
	D6	1	AFC2 SEL	AFC Angle/Bow and H correction disable	
	D7	1	V Free 2	Adaptive vertical free-run mode (by H coincidence)	
75h	D0	1	Clock SEL	$\Delta\Sigma$ D/A clock select (0: enable to select *DS D/A CLK CTL, 1: same clock as A/D)	
	D2-D7	6	H BLK F Position	H blanking (right side) timing (00: +2.6μsec — 3F: -2.6μsec)	
76h	D2-D7	6	H BLK R Position	H blanking (left side) timing (00: +2.6μsec — 3F: -2.6μsec)	
77h	D1	1	V BLK Half Kill	V blanking half H killer enable	
	D2	1	AKB Ref PLS Pos	AKB reference pulse position (0: normal, 1: 3H delay)	
	D3-D4	2	V BLK Pos	V blanking width (0: normal — 3: 3H wider, available only when AKB Ref PLS Pos="H")	
	D5	1	FBP BLK	H BLK mode select (0: adjustable by H BLK F/R Position, 1: FBP)	
78h	D0-D1	2	A/D Read Page	A/D read page select	
	D2-D3	2	V Sync LPF 1	V sync separation pre-LPF (rise edge) control (0: no filter — 3: 2μsec)	
	D4-D5	2	V Sync LPF 2	V sync separation pre-LPF (fall edge) control (0: no filter — 3: 2μsec)	
	D6-D7	2	VREF SEL	A/D reference voltage source select (use Vz)	
79h	D0-D6	7	DCT Vth	DC Transfer threshold level (0: low — 7F: high)	
7Ah	D0-D4	5	DCT Gain	DC Transfer ratio control (0: 100% — 1F: 80%)	
7Bh	D0-D7	8	AKB LIM 1	AKB LIM 1	
7Ch	D0-D7	8	AKB LIM 2	AKB LIM 2	
7Dh	D0-D7	8	AKB LIM 3	AKB LIM 3	
7Eh	D0-D7	8	AKB ADD 1	AKB ADD1	
7Fh	D0-D7	8	AKB ADD 2	AKB ADD 2	
80h	D0-D7	8	AKB COMP (R) L	AKB COMP (R) LSB	
81h	D0-D7	8	AKB COMP (G) L	AKB COMP (G) LSB	
82h	D0-D7	8	AKB COMP (B) L	AKB COMP (B) LSB	
83h	D0-D1	2	AKB COMP (R) H	AKB COMP (R) MSB	
	D2-D3	2	AKB COMP (G) H	AKB COMP (G) MSB	
	D4-D5	2	AKB COMP (B) H	AKB COMP (B) MSB	
	D6	1	AKB Enable	AKB enable (0: AKB level is held, 1: AKB level is refreshed at all time)	
	D7	1	V EN OFF	Disable to refresh ACC by vertical rate	
84h	D0-D5	6	A/D D/A Test EN	Test mode select for A/D and D/A (only factory use)	
85h	D0-D5	6	AXIS HYS	AXIS hys	
86h	D0-D5	6	ROM HYS	Rom hys	
	D6-D7	2	AVE SEL AV	Ave sel av	
87h	D0-D6	7	B2 COMP	B2 comp	
88h	D0-D3	4	U In Offset	U input DC offset level (0: - 10mV — F: +10mV)	
	D4-D7	4	V In Offset	V input DC offset level (0: - 10mV — F: +10mV)	
89h	D0	1	ACL ON	ACL enable	
	D1	1	ACL Gain	ACL gain up	
	D2-D3	2	CLK SEL SAR A/D	SAR A/D clock select (0: 2fsc, 1: 4fsc, 2: 12MHz, 3: 6MHz)	
	D4-D5	2	AKB Speed	AKB speed	
	D6-D7	2	AKB SEL	AKB control (0: AKB disable and available cutoff data, 1: AKB enable, 2: test mode)	
	D0-D1	2	DS CLK DIV SEL	$\Delta\Sigma$ D/A clock divider select (0: 1/4, 1: 1/2, 2: 1/1, 3: clock off)	
8Ah	D2	1	DS CLK Latch ON	$\Delta\Sigma$ D/A clock latched by 4fsc clock enable	
	D3	1	DS CLK Latch Pol	$\Delta\Sigma$ D/A clock latched by 4fsc clock polarity	
	D4-D5	2	VM Gain 2	VM gain2	
	D6	1	V PLS Width	V pulse width (0: standard, 1: wide)	
8Bh	D0-D7	8	AKB SWERR	AKB error detect threshold	V Latch
8Ch	D0-D7	8	AKB ERRRC	AKB error detect time	V Latch
8Dh	D0-D7	8	AKB SWPON	AKB power on threshold	V Latch
8Eh	D0-D7	8	AKB PWERRC	AKB power on time	V Latch

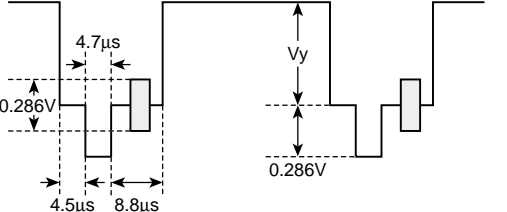
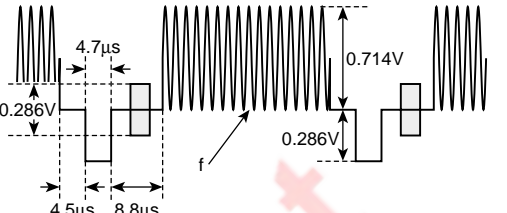
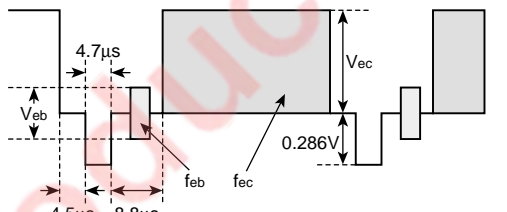
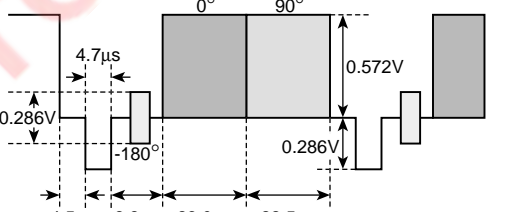
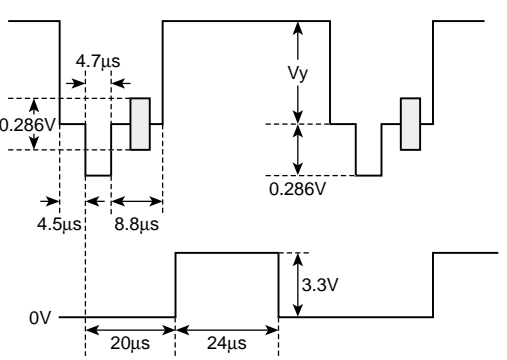
Sub address	Data	Bit	Function	Description	Note
90h	D2	1	DETNZ	Noise detector output	Read
	D4	1	AKB NG	AKB NG output	Read
	D5	1	AKB END	AKB end output	Read
	D6	1	S Det	S (Y/C) input detector output	Read
	D7	1	H COIN	Horizontal coincidence output	Read
91h	D0	1	K MONI	C-pro Killer detector output	Read
	D2	1	MV 180	Macrovision detector output	Read
	D3	1	Still Det	VCR still detector outut	Read
	D4	1	B/W Out	Burst PLL Killer detector output	Read
	D5	1	V COIN	Vertical coincidence output	Read
	D6	1	Killer Status	Color / Killer status output	Read
	D7	9	B2 ROM	B2 ROM data output	Read
92h	D0-D7				
93h	D0-D7	10	AKB A/D (R)	AKB A/D (R) output	Read
94h	D6-D7				
	D3-D4	2	C Gain	Analog ACC amp status	Read
	D5	1	AKB New (R)	AKB New (R) output	Read
95h	D0-D7	10	AKB A/D (G)	AKB A/D (G) output	Read
96h	D6-D7				
	D5	1	AKB New (G)	AKB New (G) output	Read
97h	D0-D7	10	AKB A/D (B)	AKB A/D (B) output	Read
98h	D6-D7				
	D5	1	AKB New (B)	AKB New (B) output	Read
99h	D0-D7	8	Y A/D	Y A/D output monitoring	Read
9Ah	D0-D7	8	C A/D	C A/D output monitoring	Read
9Bh	D6-D7	4	0001	Product identification	Read


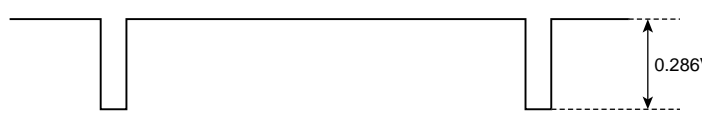
Electrical characteristics (ASIC part)

1. Test circuit



2. Input Signal

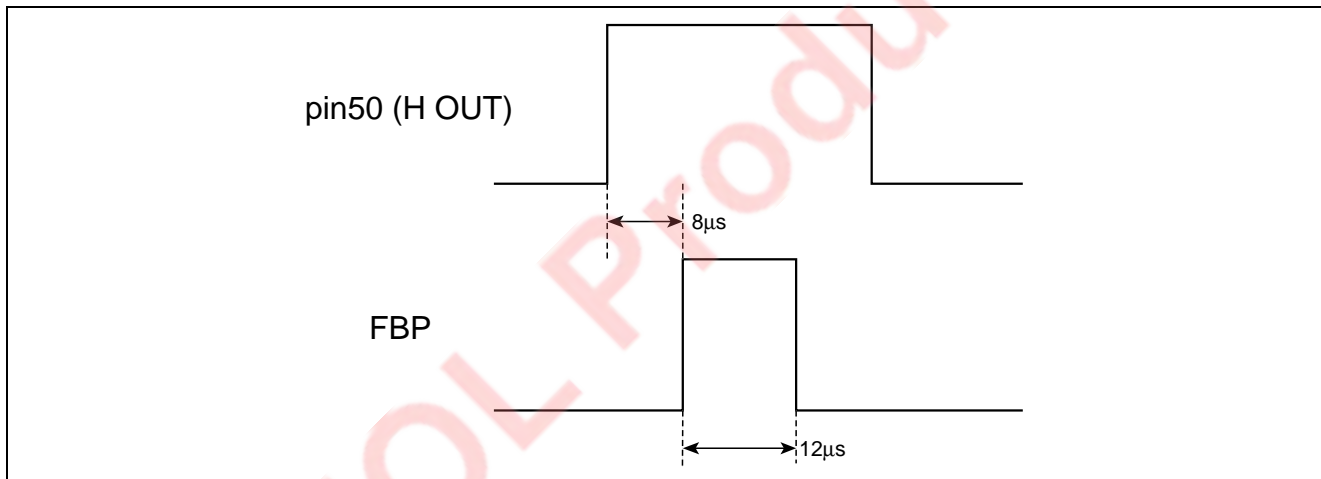
SG No.	Input signal (value at pin terminal is 50)	
SG.A	<p>NTSC system standard video signal. APL can be varied. $V_y=0.714V$ (APL 100%), unless otherwise noted. The vertical signal should be interlaced at 60Hz.</p>	
SG.B	<p>The amplitude and frequency of Luminance signal can be varied by signal SG.A. The typical amplitude is $0.714V_{p-p}$. The frequency of Luminance, (f) as stated in test.</p>	
SG.C	<p>NTSC system mono-chroma video signal. The amplitude and frequency of burst part and chroma part can be varied. The vertical signal should be interlaced at 60Hz.</p> <p>(Standard condition: $V_y=0.286V$ $V_{eb}=0.286V, V_{ec}=0.572V$ $f_{eb}=f_{ec}=3.576545MHz$)</p>	
SG.D	<p>NTSC system 2-phase chroma video signal. The vertical signal should be interlaced at 60Hz.</p> <p>(Standard condition: $V_y=0.286V$ $V_{eb}=0.286V, V_{ec}=0.572V$ $P_{eb}=-180^\circ, P_{ec1}=0^\circ, P_{ec2}=90^\circ$)</p>	
SG.E	<p>NTSC system rainbow color bar video signal. The vertical signal should be interlaced at 60Hz.</p>	
SG.F	<p>External RGB (OSD) signals and fast blanking signal should be synchronized with input video signal. $V_y=0.714V$ (APL100%), unless otherwise noted.</p>	 <p>Video input (pin16)</p> <p>Fast BLK (pin60) Half Tone (pin61) External R (pin59) External G (pin58) External B (pin57)</p>

SG No.	Input signal (value at pin terminal is 50Ω)
SG.G	Duty cycle 90%, frequency can be varied, amplitude can be varied (typ. 0.286V _{p-p}) 
SG.H	Duty cycle can be varied (typ. 95%), frequency can be varied (typ. 0.286V _{p-p}). 

3. Setup instruction for evaluation PCB

3.1 Horizontal blanking pulse adjustment

The timing and pulse width of the horizontal blanking pulse should be as shown in the following figure by adjusting the variable resistor of the single shot multi vibrator.



The variable resistor at pin15 of TTL IC 'M74LS221P' is used to fix the timing at 8s and that at pin7 is used to fix the pulse width at 12μs.

3.2. H VCO adjustment

Before measurement of M65582MF, HVCO must be adjusted by the following procedure.

Set the frequency at pin50 (H OUT) to about 15.734kHz by adjusting I²C-Bus data of H VCO control (51H D0-D7).

4. Electric characteristics

(Ta=25°C, Vdd=5.0, 3.3V)

Parameter	Symbol	Input signal		Test points	Limits			Unit	Remarks
		Pins	SG		Max.	Typ.	Min.		
Standard conditions	DC								pin48 = 1.65V
3.3V supply current	ICC33	—	—	A	140	180	220	mA	Supply of ASIC
A/D reference voltage (Top)	VRT	—	—	22	1.6	1.7	1.8	V	
A/D reference voltage (Bottom)	VRB	—	—	24	0.4	0.5	0.6	V	

Parameter	Symbol	Input signal		Test points	Limits			Unit	Remarks
		Pins	SG		Max.	Typ.	Min.		
Standard conditions of video parameter	Y								pin48 = 1.65V
CVBS OUT output level	2AG	16,21, 23	SG.A	15	1.8	2.0	2.2	Vpp	
Luminance standard output level	YOUT	16,21, 23	SG.A	31,33, 35	560	700	840	mVpp	
Video frequency characteristics	FY	16,21, 23	SG.B	31,33, 35	-5	-2	1	dB	f=5MHz
VM output level	VM	16	SG.B	24	520	650	780	mVpp	f=3.58MHz

Parameter	Symbol	Input signal		Test points	Limits			Unit	Remarks
		Pins	SG		Max.	Typ.	Min.		
Standard conditions of chroma parameter	C								pin48 = 1.65V
ACC characteristic 1	ACC1	16	SG.C	31	-3	0	3	dB	Vec, Vec : +6dB of typical input level
ACC characteristic 2	ACC2	16	SG.C	31	-3	0	3	dB	Vec, Vec : -20dB of typical input level
APC pull-in range (upper)	APCU	16	SG.C	31	-300	—	—	Hz	feb=fec : variable
APC pull-in range (lower)	APCL	16	SG.C	31	—	—	300	Hz	feb=fec : variable
Demodulation phase angle	DEMP	16	SG.D	31,35	85	90	95	deg	

Symbol	Bus condition (Input initial data, unless otherwise noted. Refer to section 8.1 for the standard data.)																																		
	00H	01H	02H	04H	05H	06H	08H	09H	0AH	0BH	0CH	0DH	0EH	10H	12H	16H	17H	18H	19H	1AH	1BH	32H	3AH	3BH	51H	65H	66H	67H	68H	69H	79H	7AH	83H	89H	
DC	00	08	6E	10	0F	6F	40	40	40	20	A0	20	80	02	80	00	C0	00	C0	00	C0	05	20	20	adj	00	83	00	8F	06	05	00	2A	00	
ICC33																																			
VRT																																			
VRB																																			

Symbol	Bus condition (Input initial data, unless otherwise noted. Refer to section 8.1 for the standard data.)																																		
	00H	01H	02H	04H	05H	06H	08H	09H	0AH	0BH	0CH	0DH	0EH	10H	12H	16H	17H	18H	19H	1AH	1BH	32H	3AH	3BH	51H	65H	66H	67H	68H	69H	79H	7AH	83H	89H	
Y	00	08	6E	10	0F	6F	40	40	40	20	A0	20	80	02	80	00	C0	00	C0	00	C0	05	20	20	adj	00	83	00	8F	06	05	00	2A	00	
2AG								00																											
YOUT								00																											
FY								00																											
VM								00																											FF

Symbol	Bus condition (Input initial data, unless otherwise noted. Refer to section 8.1 for the standard data.)																																		
	00H	01H	02H	03H	08H	09H	0AH	0BH	0CH	0DH	0EH	10H	16H	17H	18H	19H	1AH	1BH	32H	41H	42H	45H	46H	47H	48H	49H	4CH	4DH	4EH	50H	51H	5DH	83H	89H	
C	00	08	6E	08	40	40	40	20	A0	20	80	02	00	C0	00	C0	00	C0	05	01	C0	30	08	4B	00	00	91	04	14	71	adj	80	2A	00	
ACC1																																			83
ACC2																																			83
APCU																																			83
APCL																																			83
DEMP																																			

Parameter	Symbol	Input signal		Test points	Limits			Unit	Remarks
		Pins	SG		Max.	Typ.	Min.		
Standard conditions of RGB parameter	RGB								pin48 = 1.65V
Output Pedestal voltage	VPED	16	SG.A	31,33, 35	2.7	3.0	3.3	V	V _y = 0.0V
Output Blanking voltage	VBLK	16	SG.A	31,33, 35	3.1	—	3.3	V	V _y = 0.0V
Matrix ratio R/B	MTXR	16	SG.E	31,35	0.8	1.0	1.2	—	
Matrix ratio G/B	MTXB	16	SG.E	31,35	0.2	0.3	0.4	—	
AKB reference pulse output level	AKBP	16	SG.A	31,33, 35	200	300	400	mV	V _y = 0.0V
OSD output level	OSD	16,57, 58,59	SG.F	31,33, 35	480	600	720	mVpp	

Parameter	Symbol	Input signal		Test points	Limits			Unit	Remarks
		Pins	SG		Max.	Typ.	Min.		
Standard conditions of deflection parameter	DEF								pin48 = 1.65V
Horizontal free-running frequency	FH	—	—	50	15.48	15.73	15.98	kHz	
Horizontal pull-in range (upper)	FPHU	16	SG.G	50	600	—	—	Hz	Vary frequency of input signal
Horizontal pull-in range (lower)	FPHL	16	SG.G	50	—	—	-600	Hz	Vary frequency of input signal
Horizontal pulse amplitude	HOUT	16	SG.A	50	2.7	3.0	3.3	V	
Horizontal pulse width	HPTW	16	SG.A	50	17	19	22	μsec	
Vertical free-running frequency	FV	—	—	50	57	60	63	Hz	
Vertical pull-in range (upper)	FPVU	16	SG.H	44,45	—	—	64	Hz	Vary frequency of input signal
Vertical pull-in range (lower)	FPVL	51	SG.H	44,45	56	—	—	Hz	Vary frequency of input signal
Vertical output level	VOUT	16	SG.A	44,45	1.0	1.2	1.4	Vpp	
Vertical ramp output DC voltage	VDC	16	SG.A	44,45	1.5	1.7	1.9	V	
E-W output level	EWOUT	16	SG.A	47	0.3	0.4	0.5	Vpp	
E-W output DC voltage	EWDC	16	SG.A	47	0.95	1.15	1.35	V	

Symbol	Bus condition (Input initial data, unless otherwise noted. Refer to section 8.1 for the standard data.)																																		
	00H	01H	02H	04H	05H	08H	09H	0AH	0BH	0CH	0DH	0EH	10H	12H	16H	17H	18H	19H	1AH	1BH	32H	38H	3AH	3BH	51H	65H	66H	67H	68H	69H	79H	7AH	83H	89H	
RGB	00	08	6E	10	0F	40	40	40	20	A0	20	80	02	80	00	C0	00	C0	00	C0	05	A0	20	20	adj	00	83	00	8F	06	05	00	2A	00	
VPED								00																											
VBLK								00																											
MTXR								00																											
MTXB								00																											
AKBP								00																											
OSD								00																											

Symbol	Bus condition (Input initial data, unless otherwise noted. Refer to section 8.1 for the standard data.)																																			
	00H	01H	02H	05H	0FH	13H	14H	15H	32H	34H	38H	46H	4CH	4FH	50H	51H	52H	53H	54H	5DH	6AH	6BH	6CH	6DH	6EH	6FH	71H	72H	73H	74H	75H	76H	77H	8AH		
DEF	00	08	6E	0F	20	02	20	20	05	45	A0	08	91	60	71	adj	00	66	29	80	00	20	20	20	20	20	20	20	20	20	88	80	80	00	44	
FH																																				
FPHU																																				
FPHL																																				
HOUT																																				
HPTW																																				
FV																																				
FPVU																																				
FPVL																																				
VOUT																																				
VDC																																				
EWOUT																																				
EWDC																																				

5. Electrical characteristics test method

Y BLOCK

2AG: CVBS OUT output level

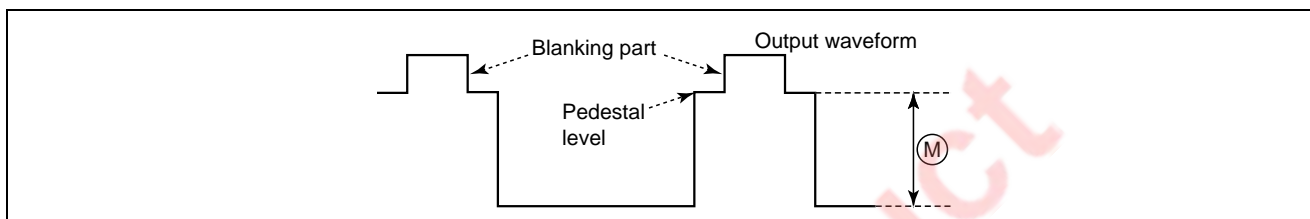
1. Input SG.A to pin 16.
2. Measure the amplitude (peak to peak) at pin 15.

Note: Use sub address 01H to select TV1 IN, TV2 IN, TV3 IN, Y(Y/C) IN, Y(YUV) IN.

YOUT: Video standard output level

1. Input SG.A to pin 16.
2. Measure the amplitude (pedestal to top part) at pins 31, 33 and 35.

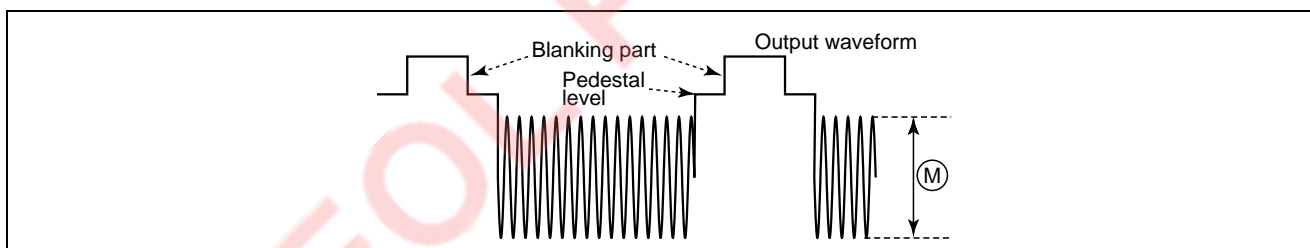
Note: Use sub address 01H to select TV1 IN, TV2 IN, TV3 IN, Y(Y/C) IN, Y(YUV) IN.



FY: Video frequency characteristic

1. Input SG.B (f=5MHz, 0.714V_{p-p}) to pin 16.
2. Measure the amplitude (peak to peak) except blanking part at pins 31, 33 and 35. The amplitude are defined as YB.
3. FY is defined as follows:

$$FY = 20 \log \frac{YB (V_{p-p})}{YOUT (V_{p-p})}$$



VM: VM output level

1. Input SG.B (f=3.58MHz, 0.714V_{p-p}) to pin 16.
2. Measure the amplitude (peak to peak) at pin 29.

C BLOCK

ACC1: ACC characteristic 1

1. Input SG.C (fec=f_{eb}+50kHz, V_{eb}, V_{ec}; standard level) to pin 16.
2. Measure the amplitude at pin 31. The amplitude is defined as C_{norR}.
3. And then, input SG.C (fec=f_{eb}+50kHz, V_{eb}, V_{ec}; +6dB) to pin 16.
4. Measure the amplitude at pin 31.
5. ACC1 is defined as follows:

$$ACC1 = 20 \log \frac{\text{measured value } (V_{p-p})}{C_{norR} (V_{p-p})}$$

ACC2: ACC characteristic 2

1. Input SG.C (fec=feb+50kHz, Veb, Vec; standard level) to pin 16.
2. Measure the amplitude at pin 31. The amplitude is defined as CnorR.
3. And then, input SG.C (fec=feb+50kHz, Veb, Vec; -20dB) to pin 16.
4. Measure the amplitude at pin 31.
5. ACC1 is defined as follows:

$$ACC2 = 20 \log \frac{\text{measured value (V}_{p-p})}{CnorR (V_{p-p})}$$

APCU: APC pull-in range (Upper)

APCL: APC pull-in range (Lower)

1. Input SG.C (fec=feb=3.579545MHz) to pin 16.
2. Increase the frequency until the waveform at pin 37 and input signal are asynchronous. And then, decrease the frequency and note the point when the waveform at pin 37 and input signal are synchronous; fU.
3. Decrease the frequency until the waveform at pin 37 and input signal are asynchronous. And then, increase the frequency and note the point when the waveform and input signal are synchronous; fL.
4. APCU and APCL are defined as follows:

$$APCU = fU - 3579545 \text{ (Hz)}$$

$$APCL = fL - 3579545 \text{ (Hz)}$$

DEMP: Demodulation phase angle

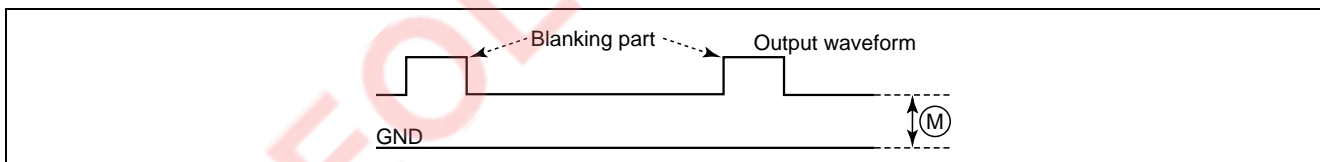
1. Input SG.D to pin 16.
2. Measure the amplitude at pin 31 (R-Y) and pin 35 (B-Y), and defined as VR-Y and VB-Y respectively.
3. DEMP is defined as follows:

$$DEMP = 180 - \text{Cos}^{-1} \frac{V_{R-Y} (mV_{p-p})}{V_{B-Y} (mV_{p-p})} \text{ (deg)}$$

RGB BLOCK

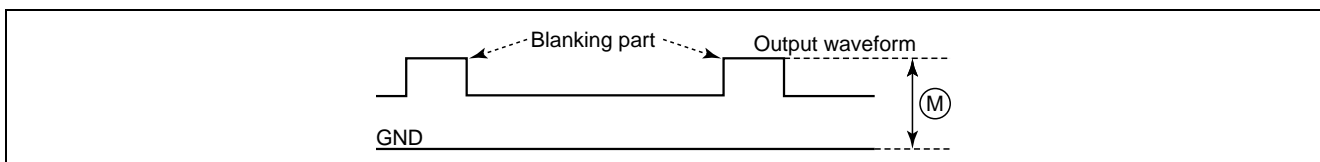
VPED: Output pedestal voltage

1. Input SG.A (Vy=0V) to pin 16.
2. Measure the voltage of pedestal part at pins 31, 33 and 35.



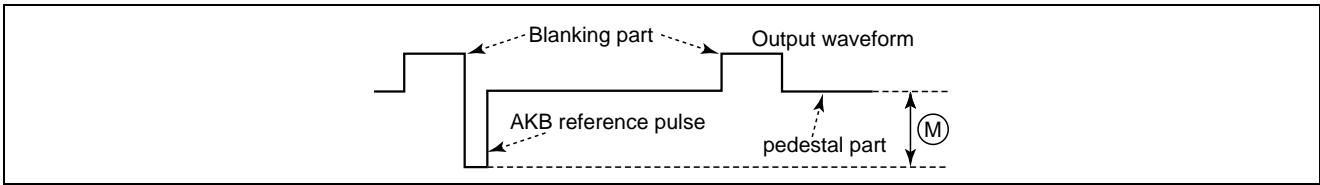
VBLK: Output blanking voltage

1. Input SG.A (Vy=0V) to pin 16.
2. Measure the voltage of blanking part at pins 31, 33 and 35.



AKBP: AKB reference pulse output level

1. Input SG.A ($V_y=0V$) to pin 16.
2. Measure the amplitude of AKB reference pulse at pins 31, 33 and 35.



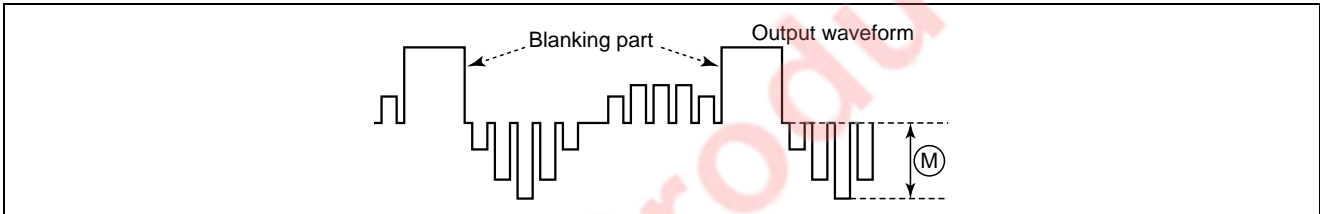
MTXRB: Matrix ratio R/B

MTXGB: Matrix ratio G/B

1. Input SG.E (rainbow color bar signal) to pin 16.
2. Measure the amplitude V_R , V_G and V_B at pins 31, 33 and 35, respectively.
3. MTXRB and MTXGB are defined as follows:

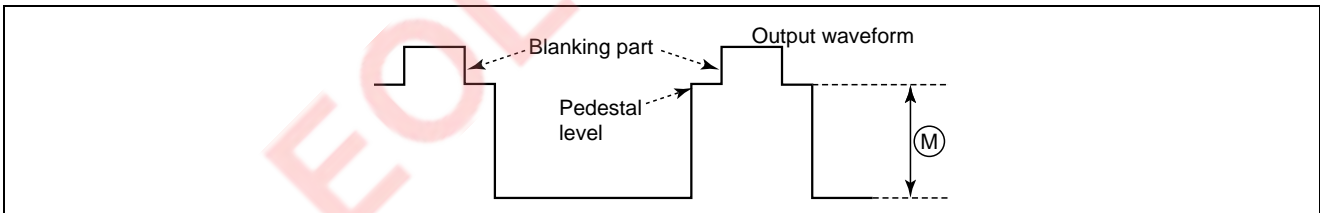
$$MTXRB = \frac{V_R (mV_{p-p})}{V_B (mV_{p-p})}$$

$$MTXGB = \frac{V_G (mV_{p-p})}{V_B (mV_{p-p})}$$



OSD: OSD output level

1. Input SG.F to pins 16, 57, 58, 59 and 60.
2. Measure the output amplitude at pins 31, 33 and 35 except that at blanking part.



DEFLECTION BLOCK

FH: Horizontal free-running frequency

1. Measure the output frequency at pin 50 when no signal is input.

FHUP: H-free-up frequency

1. Measure the output frequency at pin 50 when I2C bus data of H-free up (Sub 13h D0) is set '1'.no signal is input.
2. FHUP is defined as follows:

$$FHUP = \text{measured value(Hz)} - FH (\text{Hz})$$

FPHU: Horizontal pull-in range (Upper)

FPHL: Horizontal pull-in range (Lower)

1. Input SG.G to pin 16.
2. Change the frequency of SG.G, and measure the frequency when the output signal at pin 50 and the input signal are synchronous. The horizontal pull-in range is measured by comparing with the horizontal frequency of video signal.
3. FPHU and FPHL are defined as follows:

$$\text{FPHU} = \text{measured value (Hz)} - 15734 \text{ (Hz)}$$

$$\text{FPHL} = \text{measured value (Hz)} - 15734 \text{ (Hz)}$$

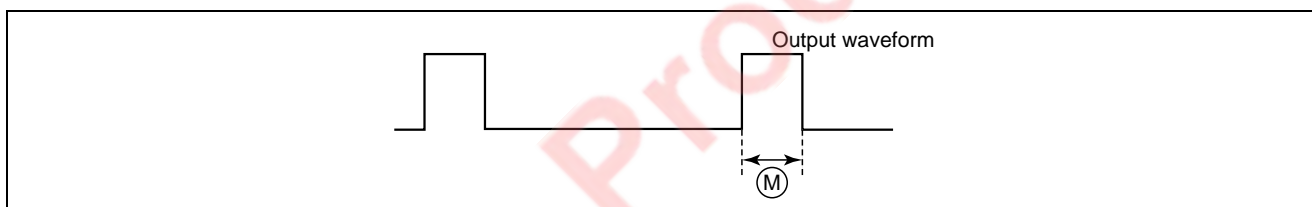
HOUT: Horizontal pulse amplitude

1. Input SG.A to pin 16.
2. Measure the amplitude at pin 50.



HPTW: Horizontal pulse width

1. Input SG.A to pin 16.
2. Measure the pulse width of output signal at pin 50.



FV: Vertical free-running frequency

1. Measure the output frequency at pins 44 and 45 when no signal is input.

FPVU: Vertical pull-in range (Upper)

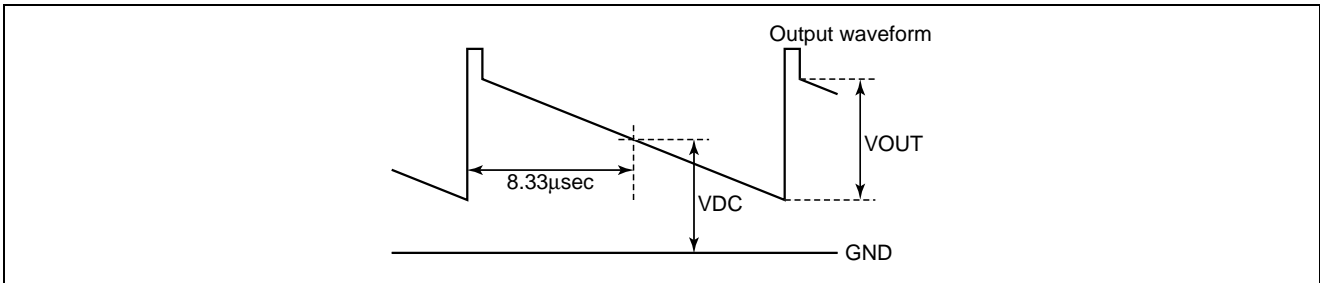
FPVL: Vertical pull-in range (Lower)

1. Input SG.H to pin 16.
2. Change the vertical frequency of SG.H, and measure the frequency when the output signal at pins 44 and 45 and the input signal are synchronous.

VOUT: Vertical ramp output level

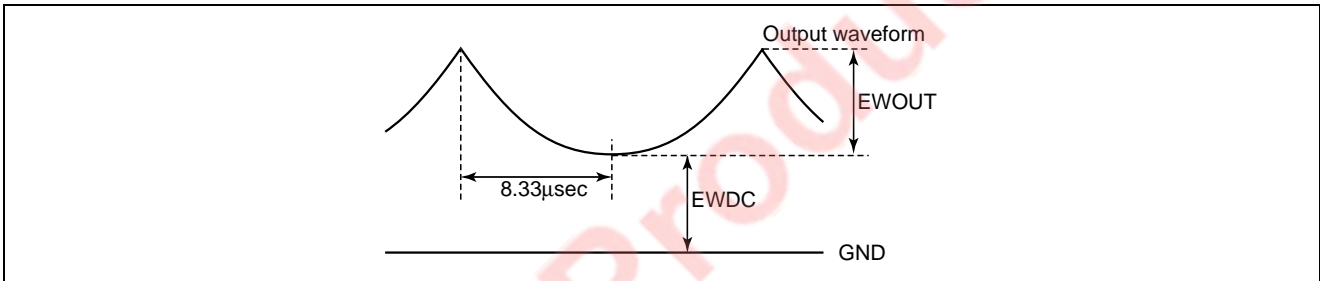
VDC: Vertical ramp output DC voltage

1. Input SG.A to pin 16.
2. Measure the output amplitude at pin 45; VOUT.
3. Measure the DC voltage at pin 45 when the timing is 8.33μsec from start point of vertical ramp; VDC.



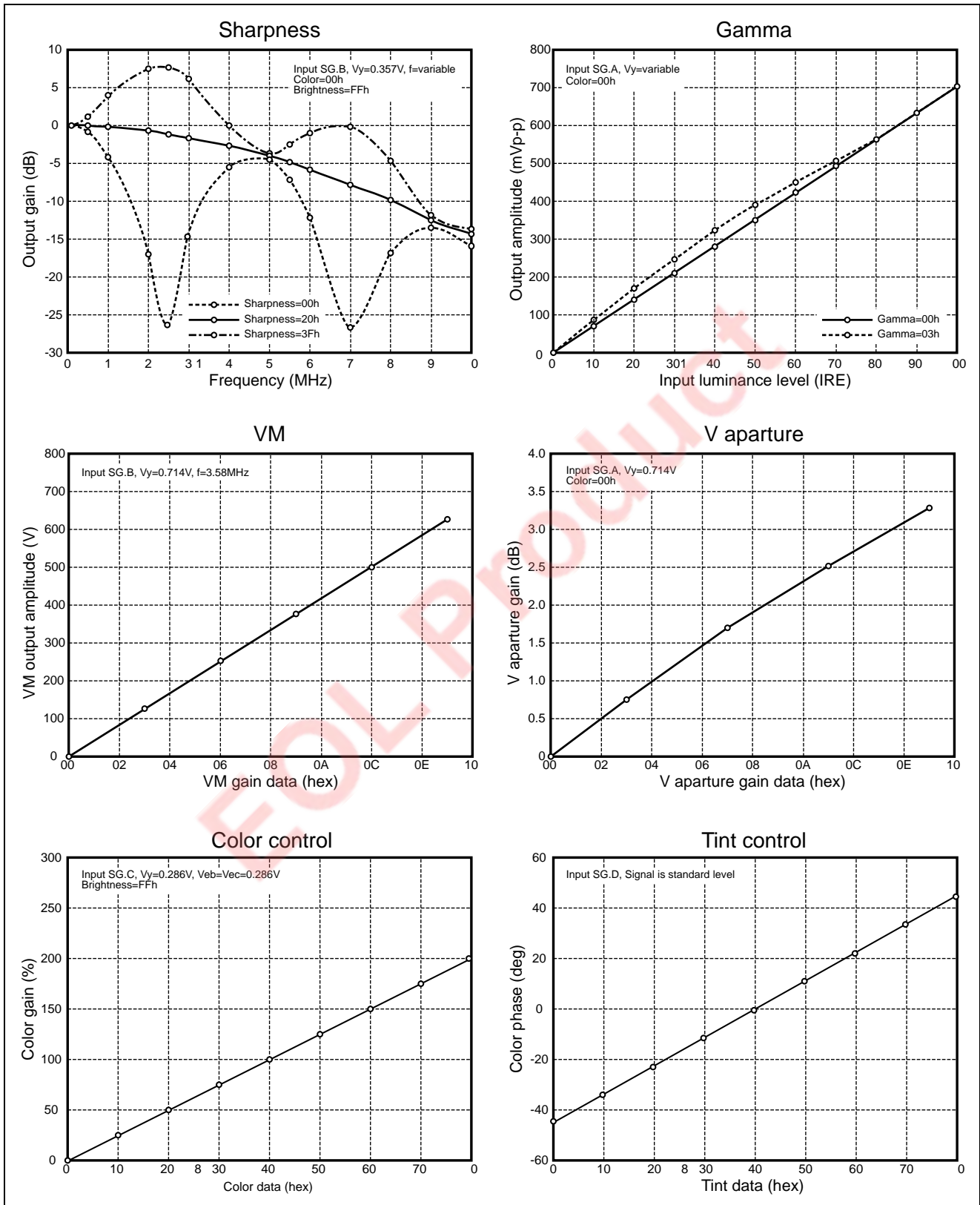
EWOUT: E-W output level

1. Input SG.A to pin 16.
2. Measure the output amplitude at pin 47; EWOUT.
3. Measure the DC voltage at pin 47 when the timing is 8.33μsec from start point of E-W; EWDC.

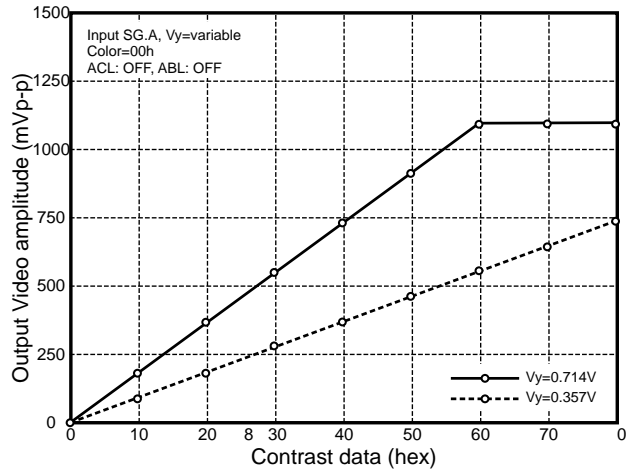


6. Example of the typical characteristics

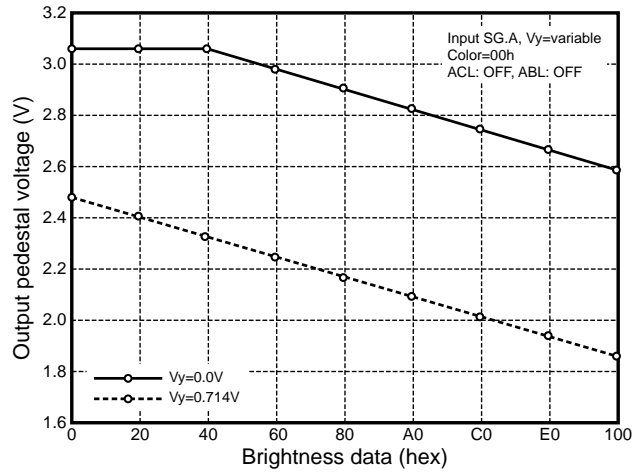
- Note: 1. These characteristics are for reference, and not guaranteed by shipment test.
 2. Bus condition is standard, unless otherwise noted (Refer to page 8).



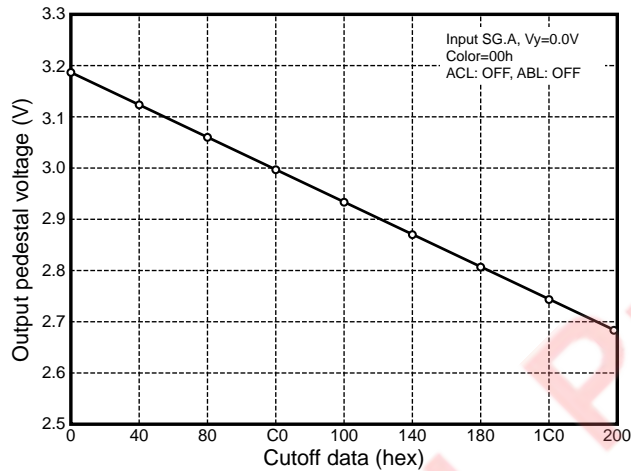
Contrast control



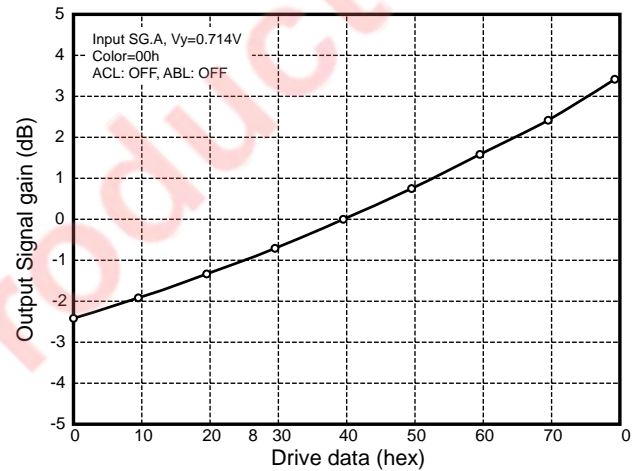
Brightness control



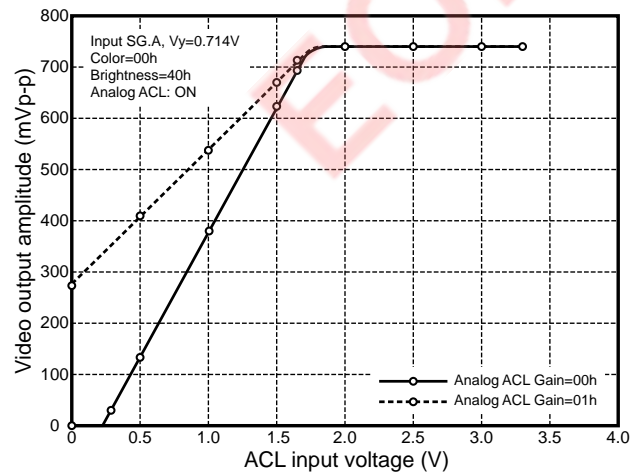
Cutoff control



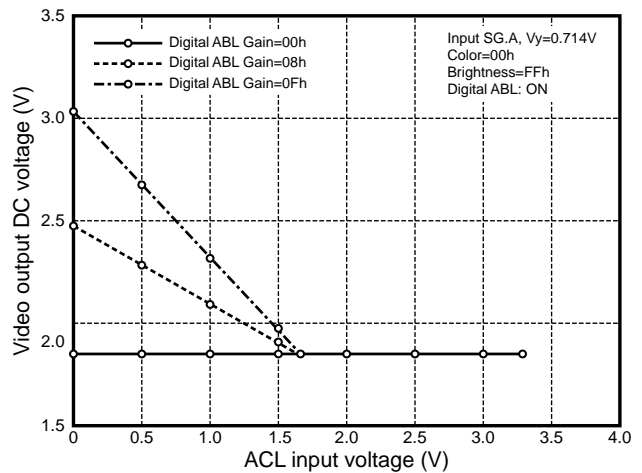
Drive control

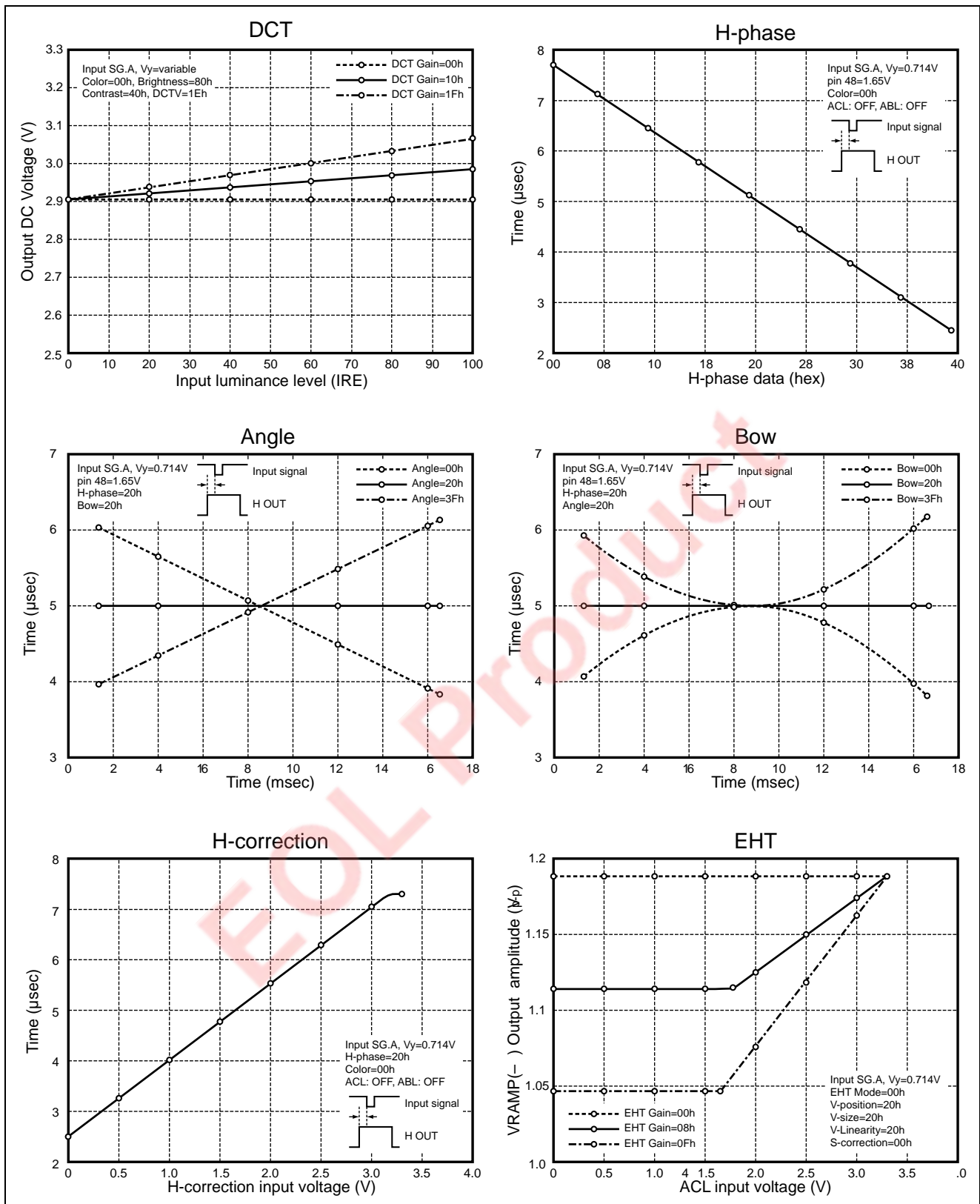


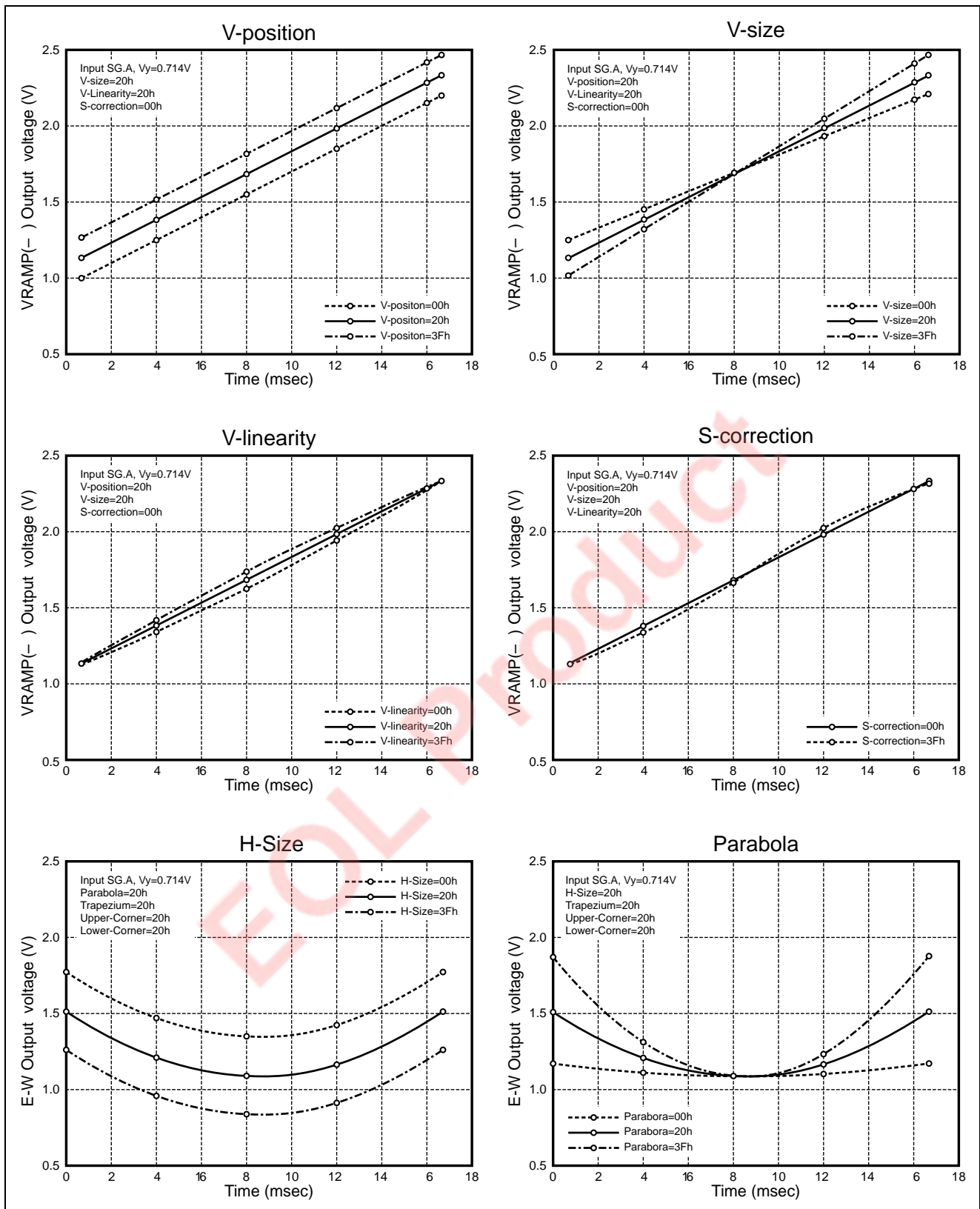
ACL characteristic

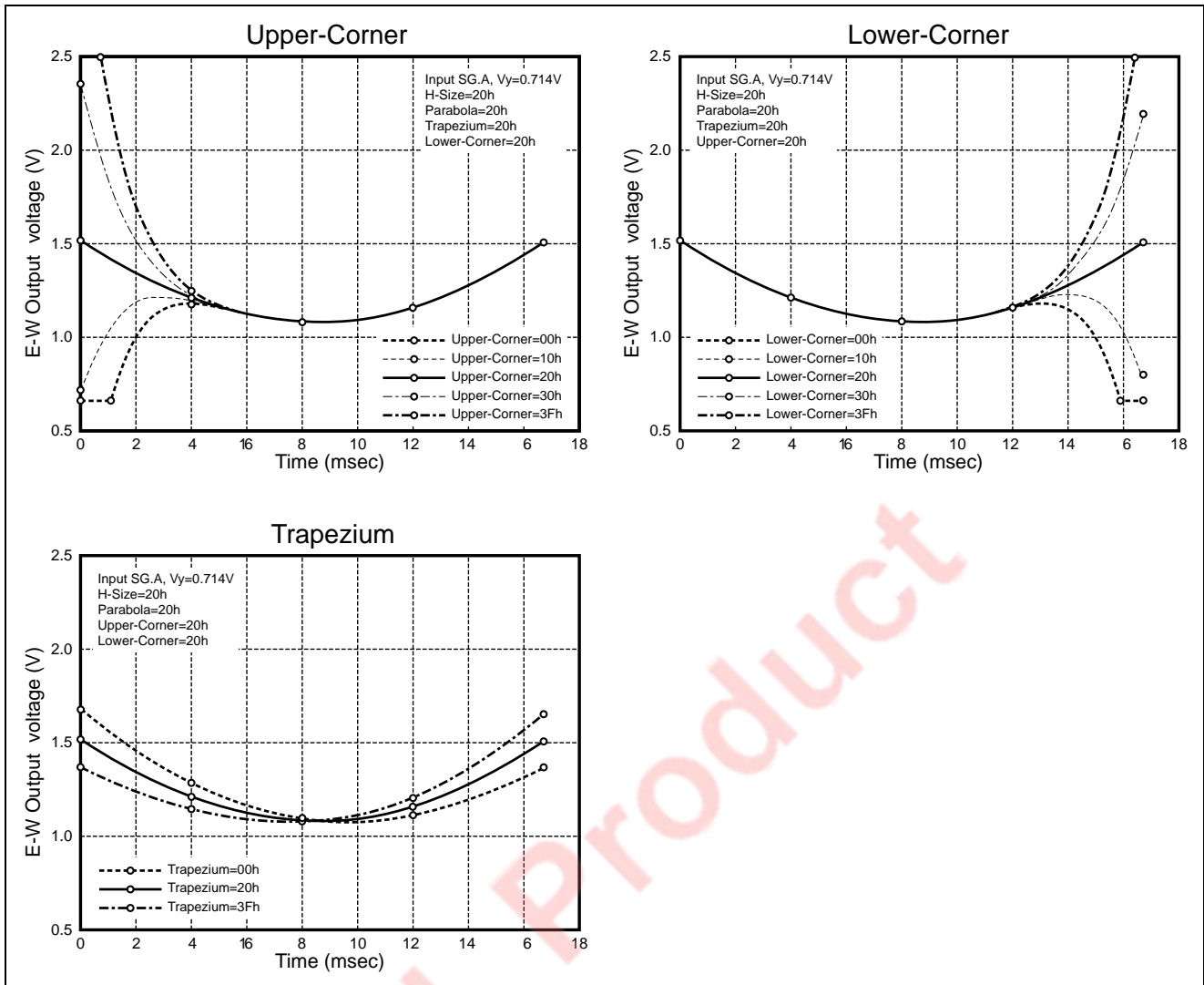


ABL characteristic









Electrical characteristics (MCU part)

1. Electrical characteristics

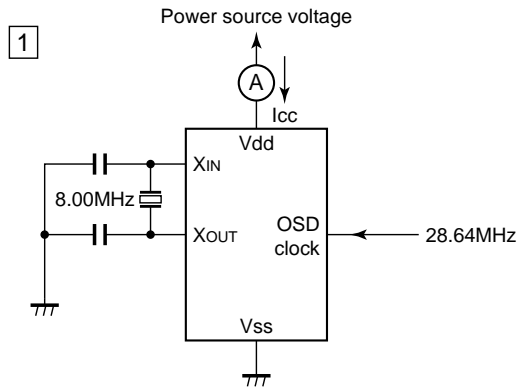
(VDD=55%, VSS=0V, f(XIN)=8MHz, Ta=-20°C to 70°C, unless otherwise noted)

Parameter	Symbol	Limits			Unit	Test conditions	Test Circuit	
		Min.	Typ.	Max.				
Power source current System operation	Icc		15	30	mA	VDD=5.25V, f(XIN)=8MHz	1	
				30	45			OSD ON
				60	200	μA	VDD=5.25V, f(XIN)=0, f(XCIN)=32kHz, OSD OFF, Data slicer OFF, Low-power dissipation mode set (CM5="0", CM6="1")	
			Wait mode	2	4	mA	VDD=5.25V, f(XIN)=8MHz	
				25	100		μA	VDD=5.25V, f(XIN)=0, f(XCIN)=32kHz, OSD OFF, Data slicer OFF, Low-power dissipation mode set (CM5="0", CM6="1")
		1	10		VDD=5.25V, f(XIN)=0, f(XCIN)=0			
HIGH output voltage P10-P16, P20-P27, P40-P45	VOH	2.4		V	VDD=4.75V, IOH=-0.5mA	2		
LOW output voltage P00-P07, P10, P15, P16, P20-P27, P40-P45	VOL		0.4	V	VDD=4.75V, IOH=0.5mA			
LOW output voltage P11-P14,			0.4		VDD=4.75V	IOL=3mA		
			0.6			IOL=6mA		
Hysteresis (See note 1) RESET, INT1, INT2, INT3, TIM2, TIM3, SIN, SCLK, SCL1, SCL2, SDA1, SDA2	VT+ VT-			1.3	V	VDD=5.0V	3	
HIGH input leak current P00-P07, P10-P16, P20-P27, P40-P45, RESET	IIZH			5	μA	VDD=5.25V, VI=5.25V	4	
LOW input leak current P00-P07, P10-P16, P20-P27, P40-P45, RESET	IIZL			5	μA	VDD=5.25V, VI=0V	4	
I ² C-BUS-BUS switch connection resistor (between SCL1 and SCL2, SDA1 and SDA2)	RBS			130	Ω	VDD=4.75V	5	

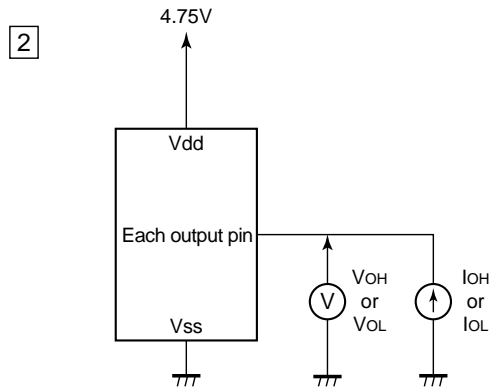
Notes : 1. P06, P07, P23-P25 have the hysteresis when these pins are used as interrupt input pins or timer input pins. P11-P14

have the hysteresis when these pins are used as multi-master I²C-BUS interface ports. P20-P22 have the hysteresis when these pins are used as serial I/O pins.

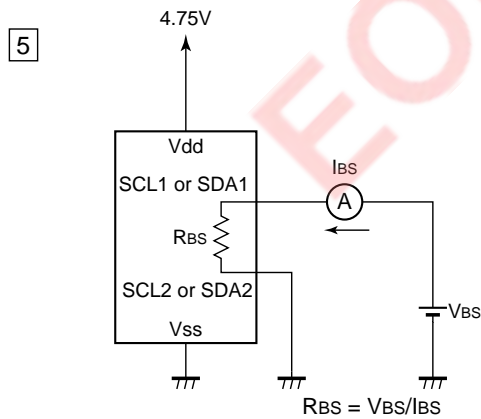
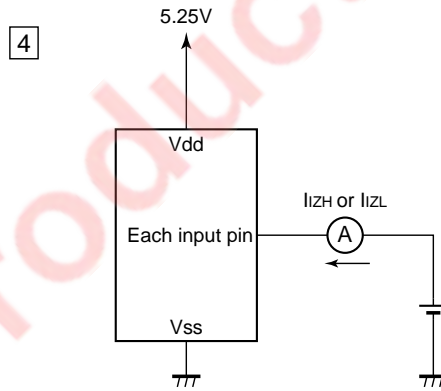
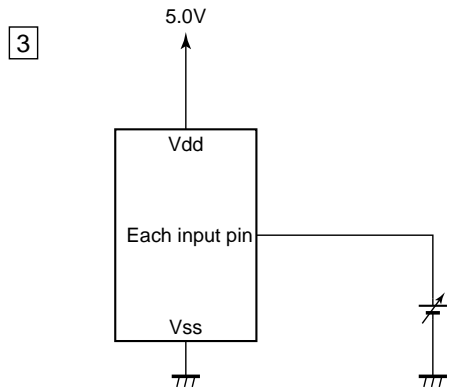
2. Test circuit



Pin Vdd is made the operation state and is measured the circuit, with a ceramic resonator.



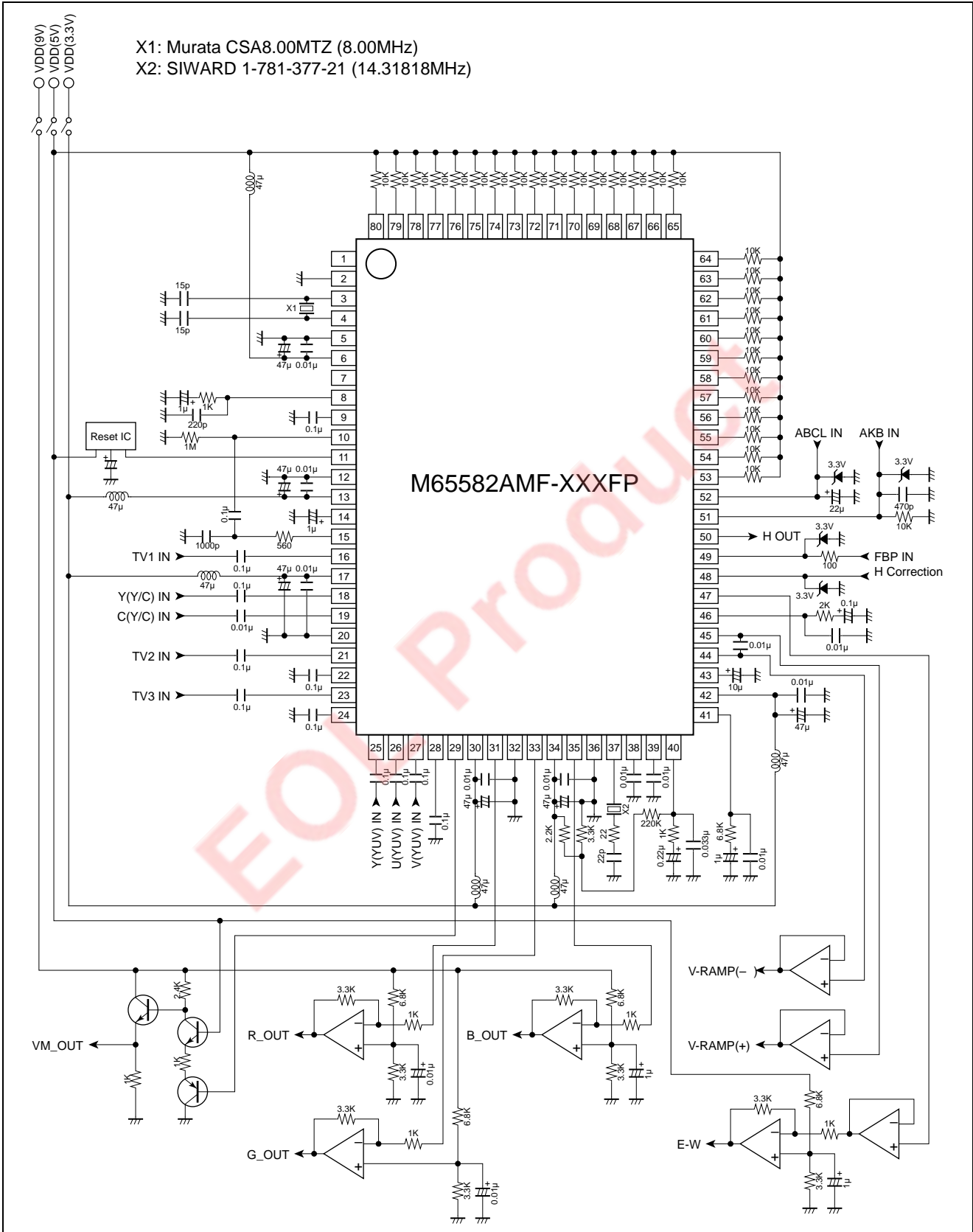
After setting each output pin to HIGH level when measuring Voh and to LOW level when measuring Vol, each pin is measured



After setting each output pin OFF state, each pin is measured.
(4, 5)

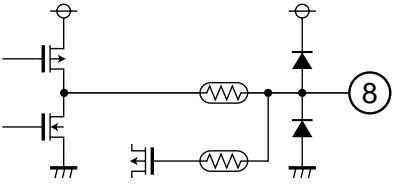
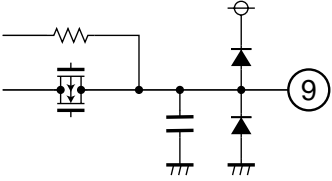
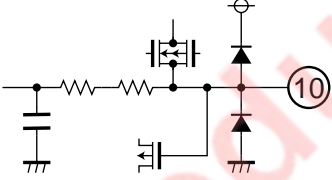
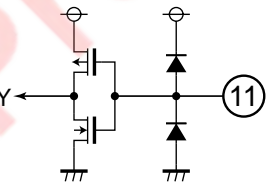
Application example

Note: If you will apply this application example to practice, please study it fully.


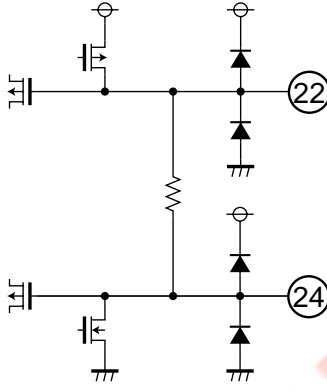
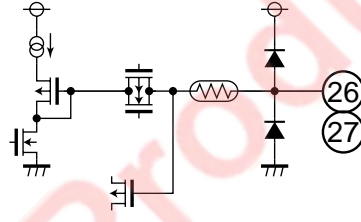
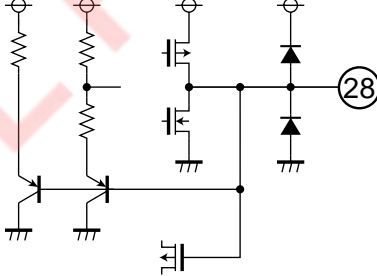
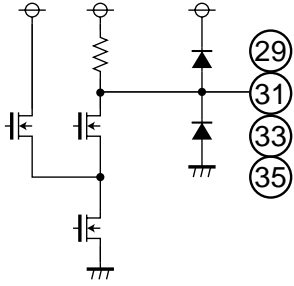



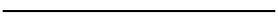


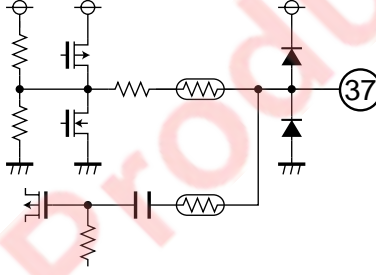
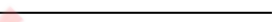
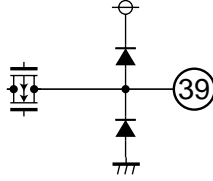
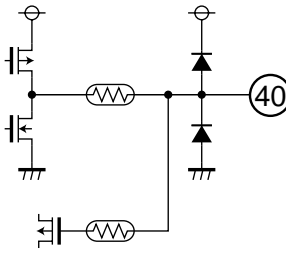
Description of Pin

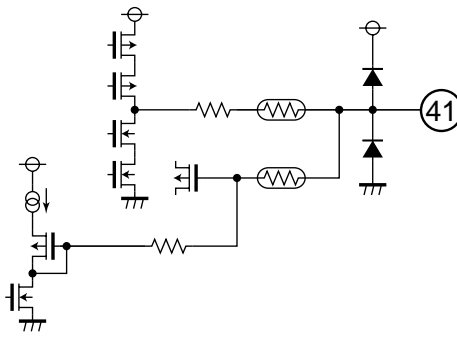
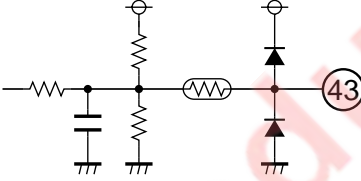
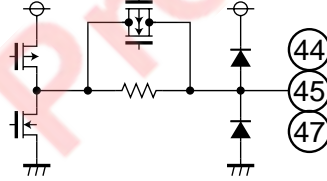
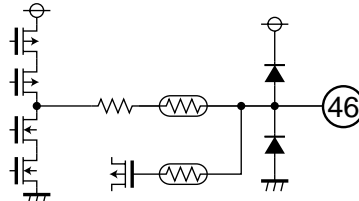
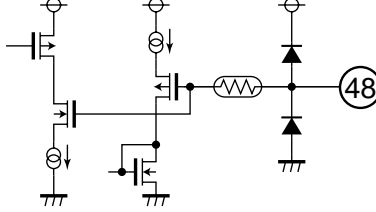
Pin No.	Name	Peripheral circuit of pins	Note
2	CN VSS		0V
3 4	X IN X OUT		
5	Vss (MCU)	_____	Power source for MCU. 0V
6	Vdd (MCU)	_____	Power source for MCU. 5.0V ± 5%
7	FILT		

Pin No.	Name	Peripheral circuit of pins	Note
8	HLF		Impedance=N.A. (Additional filter on PCB board)
9	VHOLD		
10	CVIN		
11	RESET		CMOS INPUT (Impedance>100kΩ) V _{OL} = 0V : Reset state V _{OH} = 5V : Release from Reset state
12	Vss(Digital)	_____	Power source for Digital blocks. 0V
13	Vdd(Digital)	_____	Power source for Digital blocks. 3.3V ± 5%

Pin No.	Name	Peripheral circuit of pins	Note
14	DCT FILTER		Impedance=N.A.
15	CVBS OUT		Impedance=150Ω DC : 0.55V (sync) AC : 1.75V _{p-p} (typ.)
16 18 21 23 25	TV1 IN Y(Y/C) IN TV2 IN TV3 IN Y(YUV) IN		Impedance=N.A. DC : 0.5V (sync) AC : 1.0V _{p-p} (typ.)
17	Vdd(Input)	_____	Power source for A/D etc. 3.3V ± 5%
19	C(Y/C) IN		Impedance=5kΩ DC : 1.0V AC : 0.286V _{p-p} (burst)

Pin No.	Name	Peripheral circuit of pins	Note
20	Vss(Input)		Power source for A/D etc. 0V
22 24	VRT VRB		Impedance=50Ω DC : 1.7V (VRT) 0.5V (VRB)
26 27	U(YUV) IN V(YUV) IN		Impedance=N.A. DC : 1.0V AC : 0.7V _{p-p} (typ.)
28	VZ OUT		Impedance=400Ω DC : 2.05V
29 31 33 35	VM R OUT G OUT B OUT		Impedance=500Ω DC : 1.65V (VM) 3V (blinking)

Pin No.	Name	Peripheral circuit of pins	Note
30	Vdd(Output)		Power source for D/A etc. 3.3V±5%
32	Vss(Output)		Power source for D/A etc. 0V
34	Vdd(VCXO)		Power source for VCXO etc. 3.3V±5%
36	Vss(DEF)		Power source for Deflection block. 0V
37	XTAL (NTSC)		Impedance≈1kΩ
38	N.C.		
39	TEST		Not useful (Connect 0.01μF or more capacitor externally)
40	APC FILTER		Impedance=N.A. (Additional filter on PCB board)

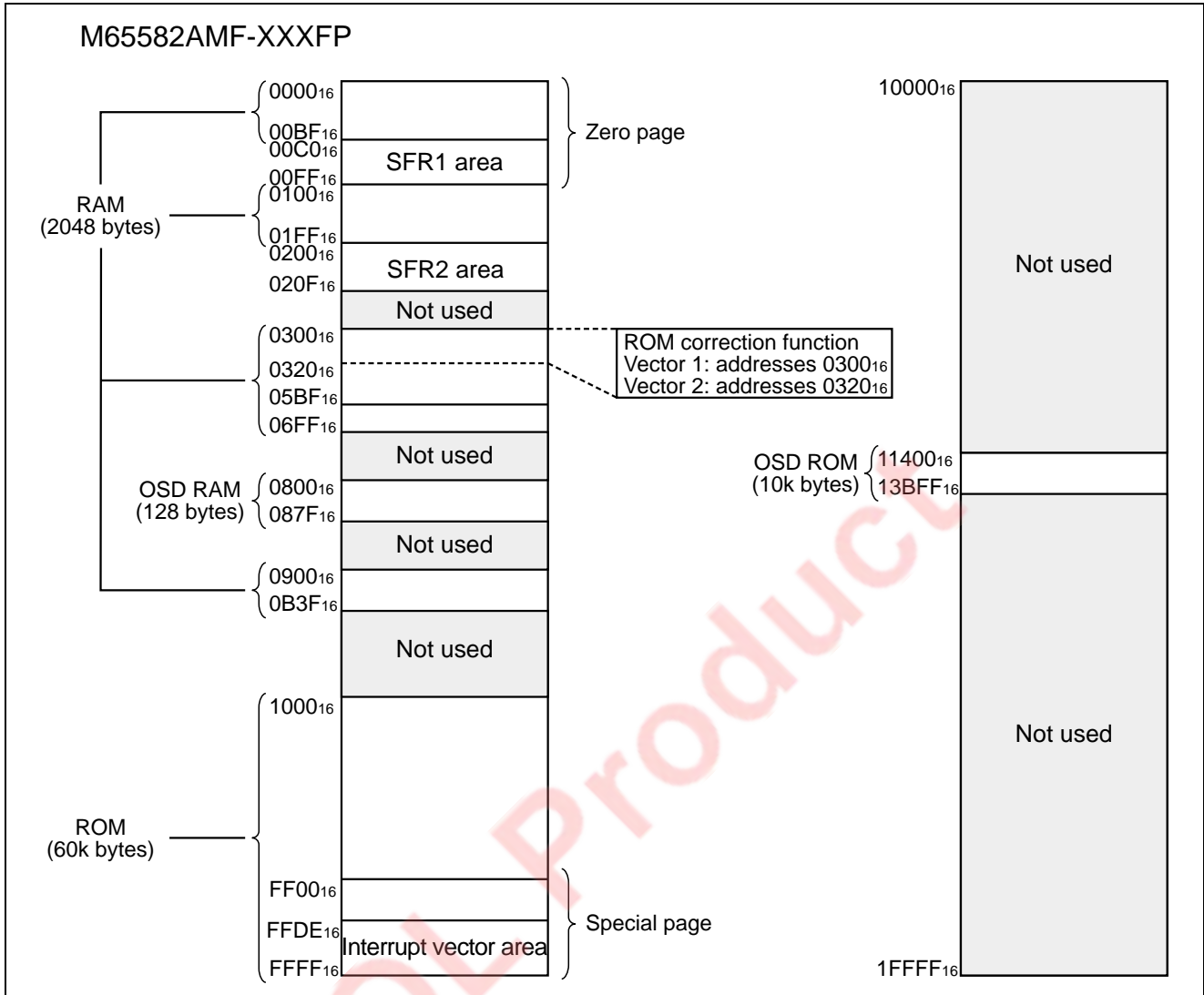
Pin No.	Name	Peripheral circuit of pins	Note
41	AFC1 FILTER		Impedance=N.A. (Additional filter on PCB board) DC : 1.65V
42	Vdd(DEF)	_____	Power source for Deflection blocks. 3.3V±5%
43	VRAMP C		Impedance≈12.5kΩ
44 45 47	VRAMP(-) VRAMP(+) E-W		Impedance≈20kΩ AC : 1.0Vpp (typ.)
46	HVCO FB		Impedance=N.A. (Additional filter on PCB board) DC : 1.65V
48	H CORRE		Impedance>1MΩ Input voltage range : 0 to 3.3V 0V : H OUT +2.2μsec 3.3V : H OUT - 2.2μsec

Pin No.	Name	Peripheral circuit of pins	Note
49	FBP IN		<p>CMOS INPUT (Impedance > 100kΩ)</p> <p>$V_{IL}=0V$: RGB output $V_{IH}=3.3V$: Blanking</p>
50	H OUT		<p>CMOS IN/OUT 1 (Impedance > 100kΩ (input) Impedance < 100Ω (output))</p>
51 52	AKB IN ACL IN		<p>Input voltage range : 0 to 3.3V</p>
53 54 55 56	P14/SDA2 P13/SDA1 P12/SCL2 P11/SCL1		<p>CMOS IN/OUT 1 (Impedance > 100kΩ (input) Impedance < 100Ω (output))</p>

Pin No.	Name	Peripheral circuit of pins	Note
53 54 55 56	P14/SDA2 P13/SDA1 P12/SCL2 P11/SCL1		CMOS IN/OUT 1 (Impedance > 100kΩ (input) Impedance < 100Ω (output))
57 58 59 60 61 65 67	P40 P41 P42 P43 P10 P44 P45		CMOS IN/OUT 1 (Impedance > 100kΩ (input) Impedance < 100Ω (output))
62 63 64 71	P00/PWM0 P01/PWM1 P02/PWM2 P07/INT1		CMOS IN/OUT (Impedance > 100kΩ (input) Impedance < 100Ω (output))
66 68 69 70	P03/PWM3/AD1 P04/PWM4/AD2 P05/AD3 P06/INT2/AD4		CMOS IN/OUT (Impedance > 100kΩ (input) Impedance < 100Ω (output))

Pin No.	Name	Peripheral circuit of pins	Note
72 73 77 78 79	P15 P16 P23/TIM3 P24/TIM2 P25/INT3		<p>CMOS IN/OUT 1</p> <p>(Impedance > 100kΩ (input) Impedance < 100Ω (output))</p>
74 75 76	P20/SCLK/AD5 P21/SOUT/AD6 P22/SIN/AD7		<p>CMOS IN/OUT</p> <p>(Impedance > 100kΩ (input) Impedance < 100Ω (output))</p>
80 1	P26/XCIN P27/XCOUT		

Memory Map



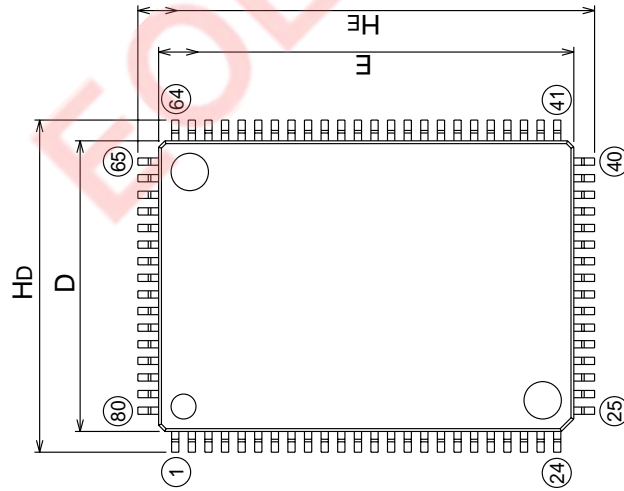
Package Dimensions

80P6U-A

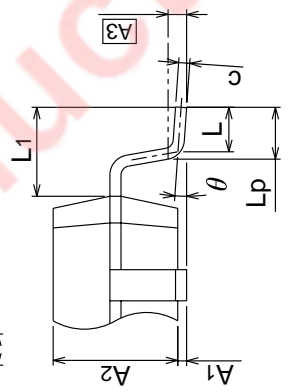
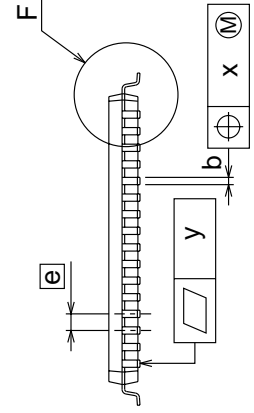
(MMP)

Plastic 80pin 14X 20mm body LQFP

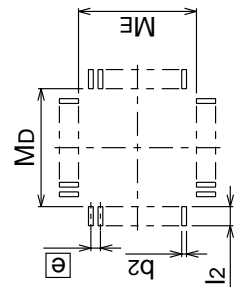
EIAJ Package Code LQFP80-P-1420-0.8	JEDEC Code —	Weight(g)	Lead Material Cu Alloy
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Under Planning



Detail F



Recommended Mount Pad

Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	1.6
A1	0.05	0.125	0.2
A2	—	1.4	—
b	0.32	0.37	0.47
c	0.105	0.125	0.175
D	13.9	14.0	14.1
E	19.9	20.0	20.1
e	—	0.8	—
HD	15.8	16.0	16.2
HE	21.8	22.0	22.2
L	0.35	0.5	0.65
L1	—	1.0	—
Lp	0.45	0.6	0.75
A3	—	0.25	—
x	—	—	0.2
y	—	—	0.1
θ	0°	—	8°
b2	—	0.225	—
l2	10	—	—
MD	—	14.4	—
ME	—	20.4	—

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